



AGIPD

AGIPD Meeting: November 2015

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OUTLINE



1. GAIN / Noise Map

Problem of the gain non uniformity
New Measurements

2. DR Scan / Linearity / Noise

3. Burst Mode

Settling time of V_{refpxb} ...

4. Droop

5. Chip Probing/ Bumpbond



1

GAIN / Noise Map

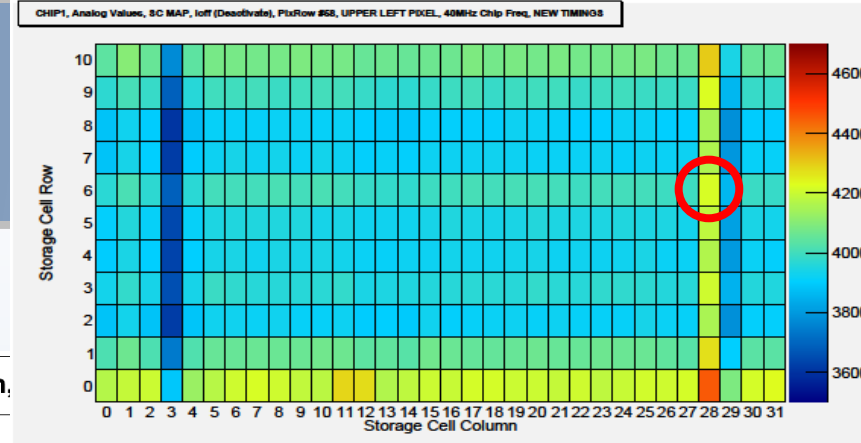


GAIN/NOISE: MEASUREMENT CONDITIONS

- Mo 17keV
- 1 Row of storage cell acquired for Chip 6 + 2 SC for Chip 1 (2 chiptest boxes died during acquisition) -> No Cooling (Chip Temp ~60/70 °C)
- Chip Running @40MHz
- Integration Time: 10 μ s
- CDS gain HIGH and LOW
- Noise and baseline acquired with 200ns Integration Time
- Depletion Voltage: 250V
- Biasing: External

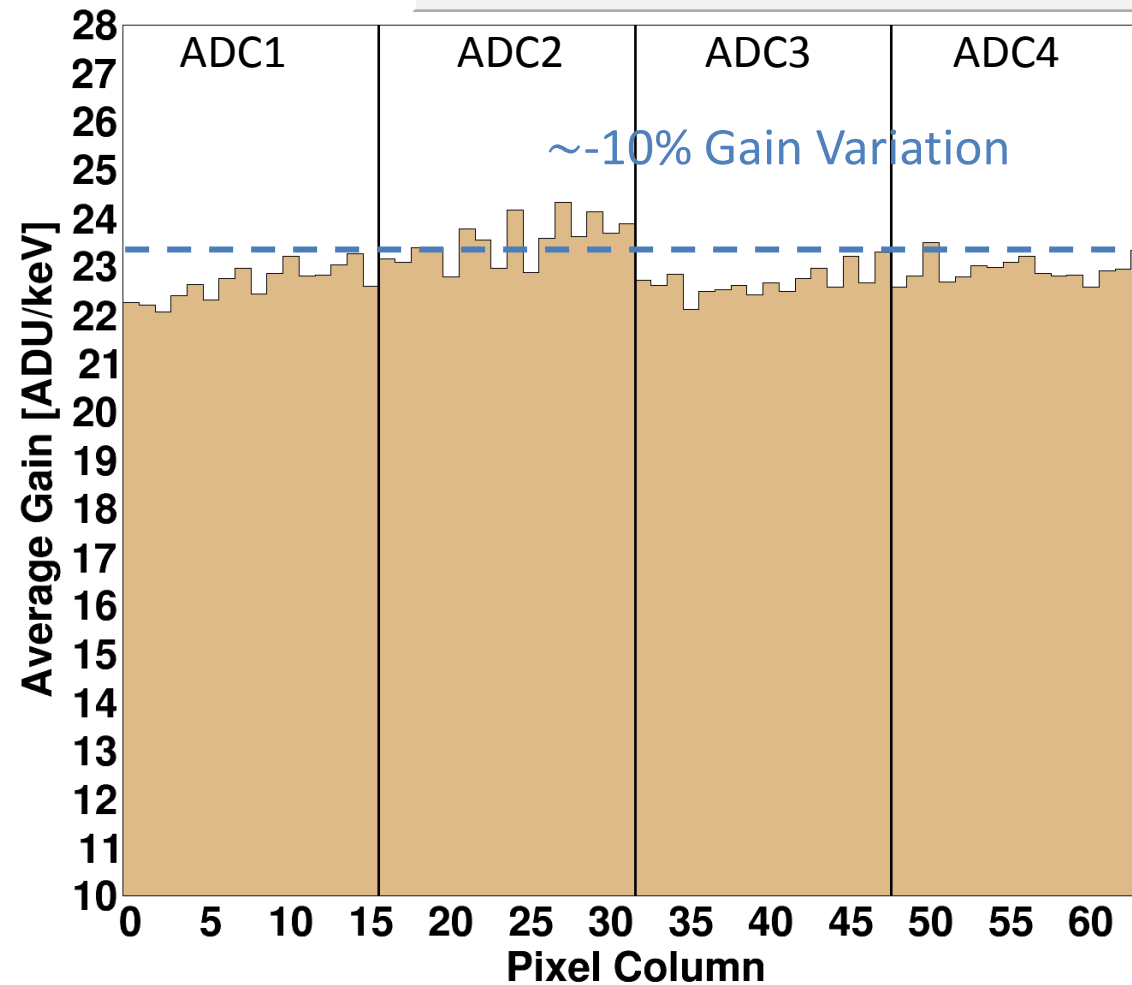
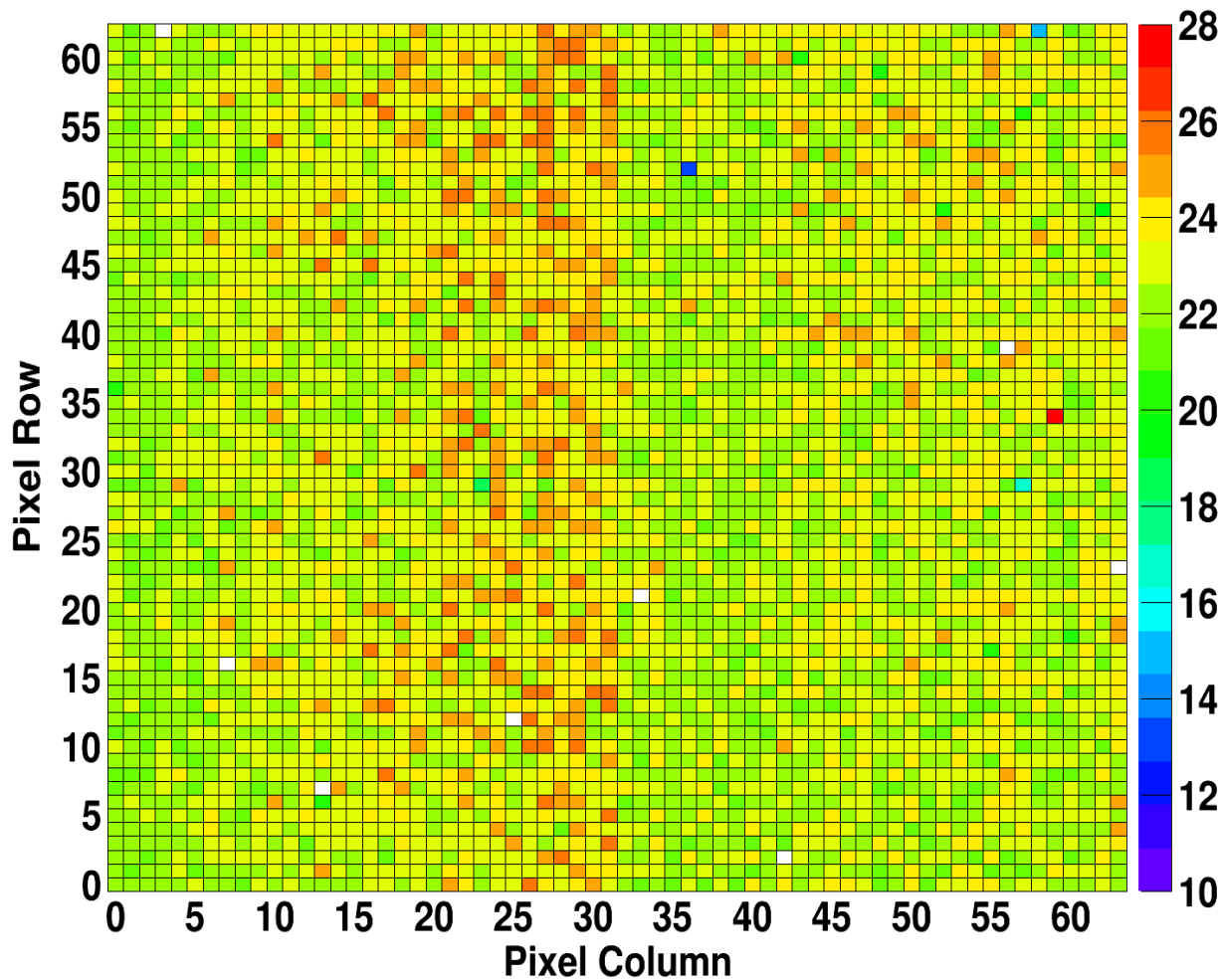
GAIN MAP, Chip 1

SC220, Row6 Col 28

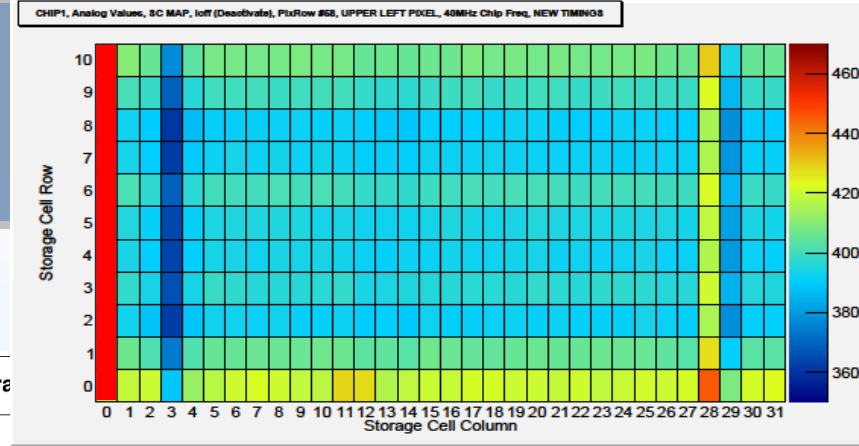


Gain Map, CDS Gain High, 1 Mo Peak, SC 220, CHIP1

Average Gain, CDS Gain High,

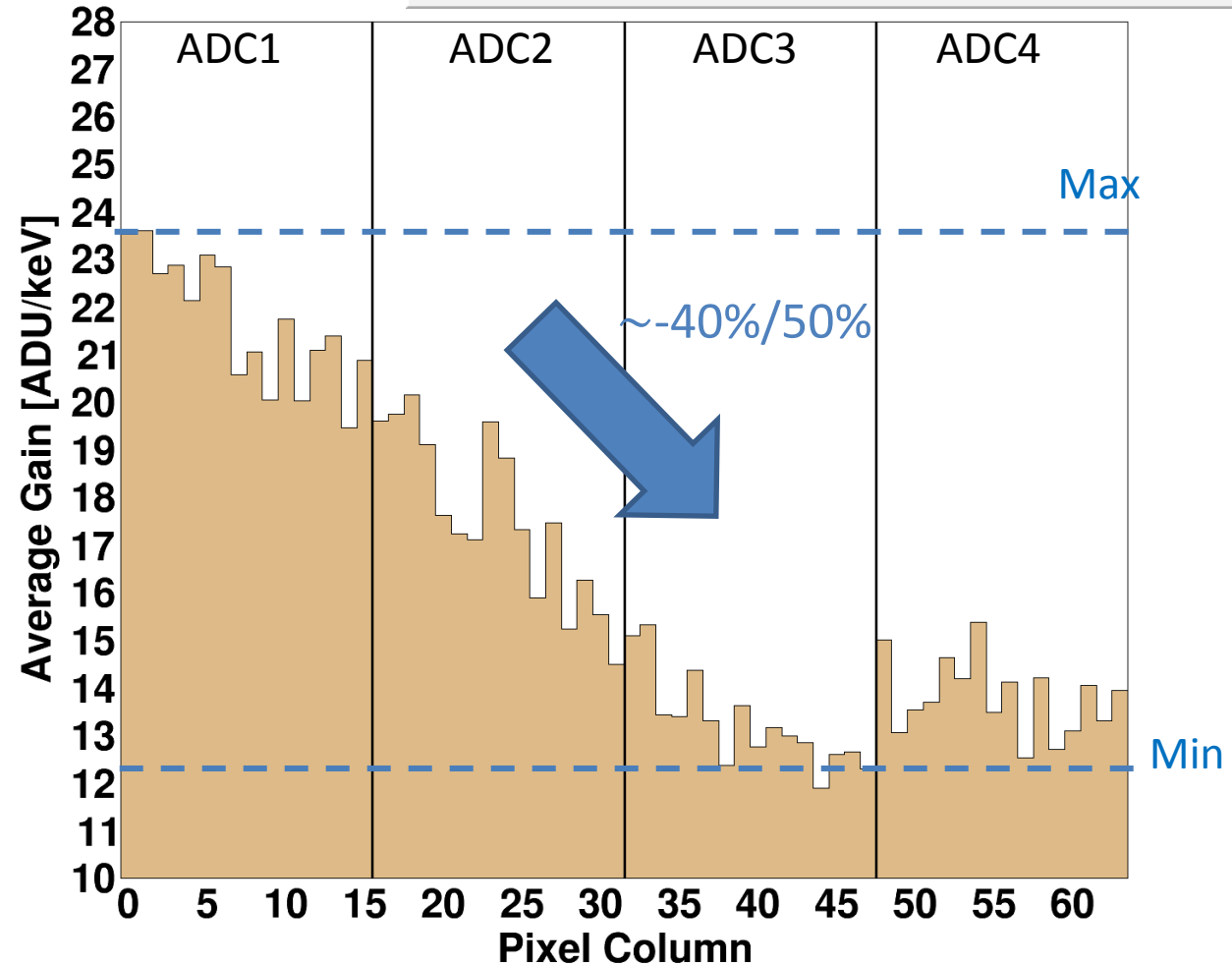
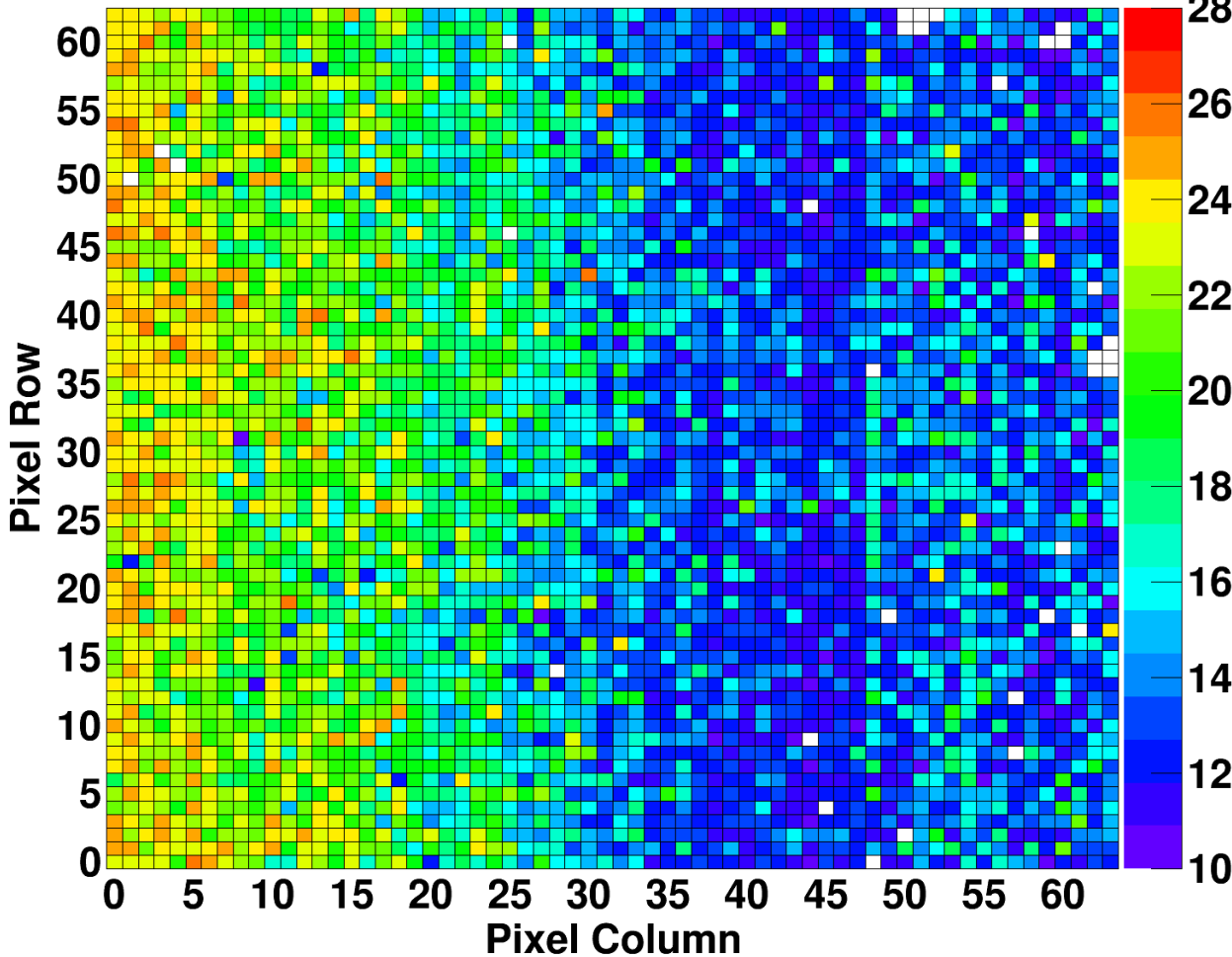


GAIN MAP, Chip 6 SC64, Row2 Col 0

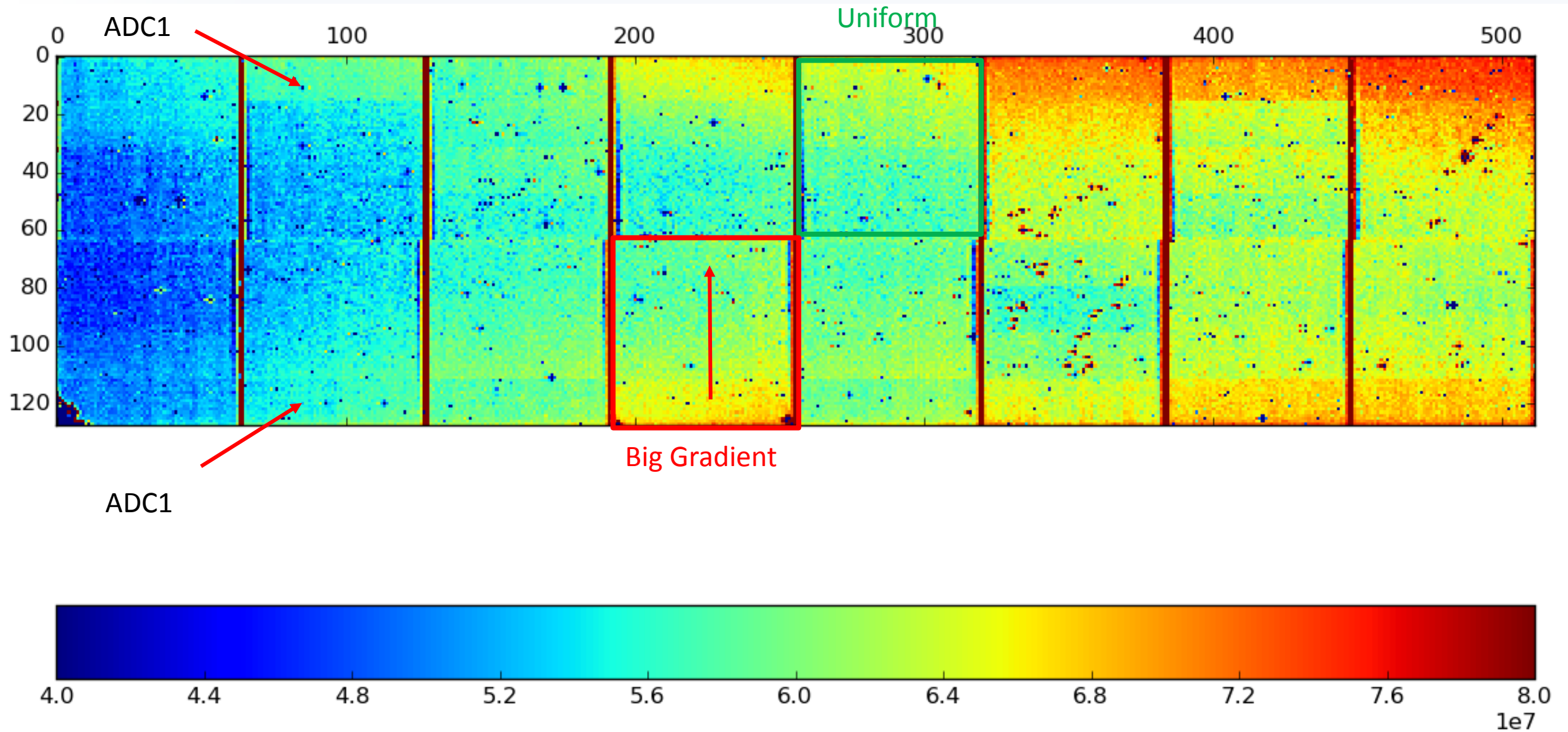


Gain Map, CDS Gain High, Storage Cell Row 2 Column 0, Mo 17.5keV, CHIP6

Average Gain, CDS Gain High, Storage Cell Row 2 Column 0, Mo 17.5keV, CHIP6

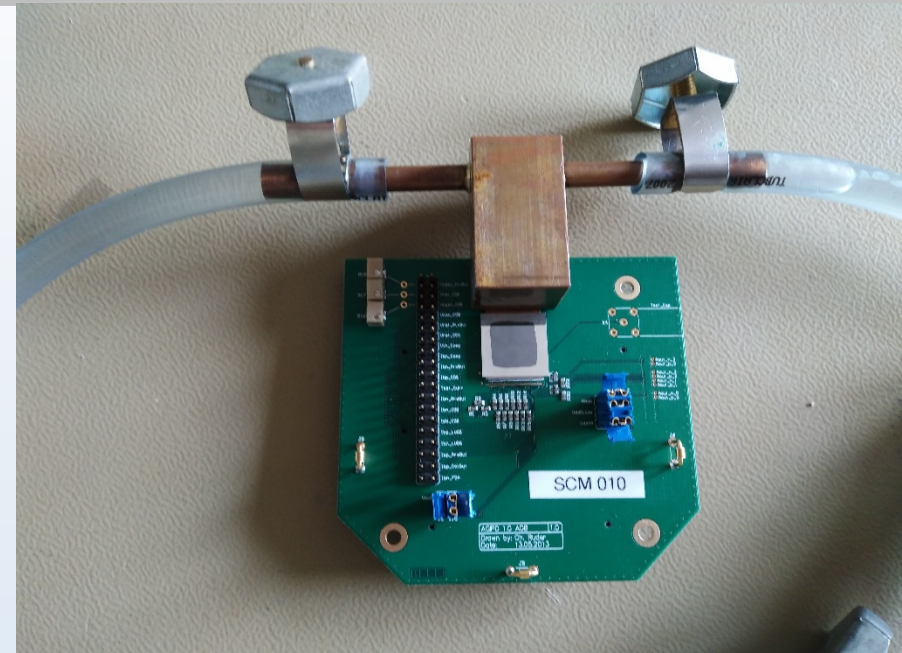


Module Map with Photons



GAIN/NOISE: MEASUREMENT CONDITIONS

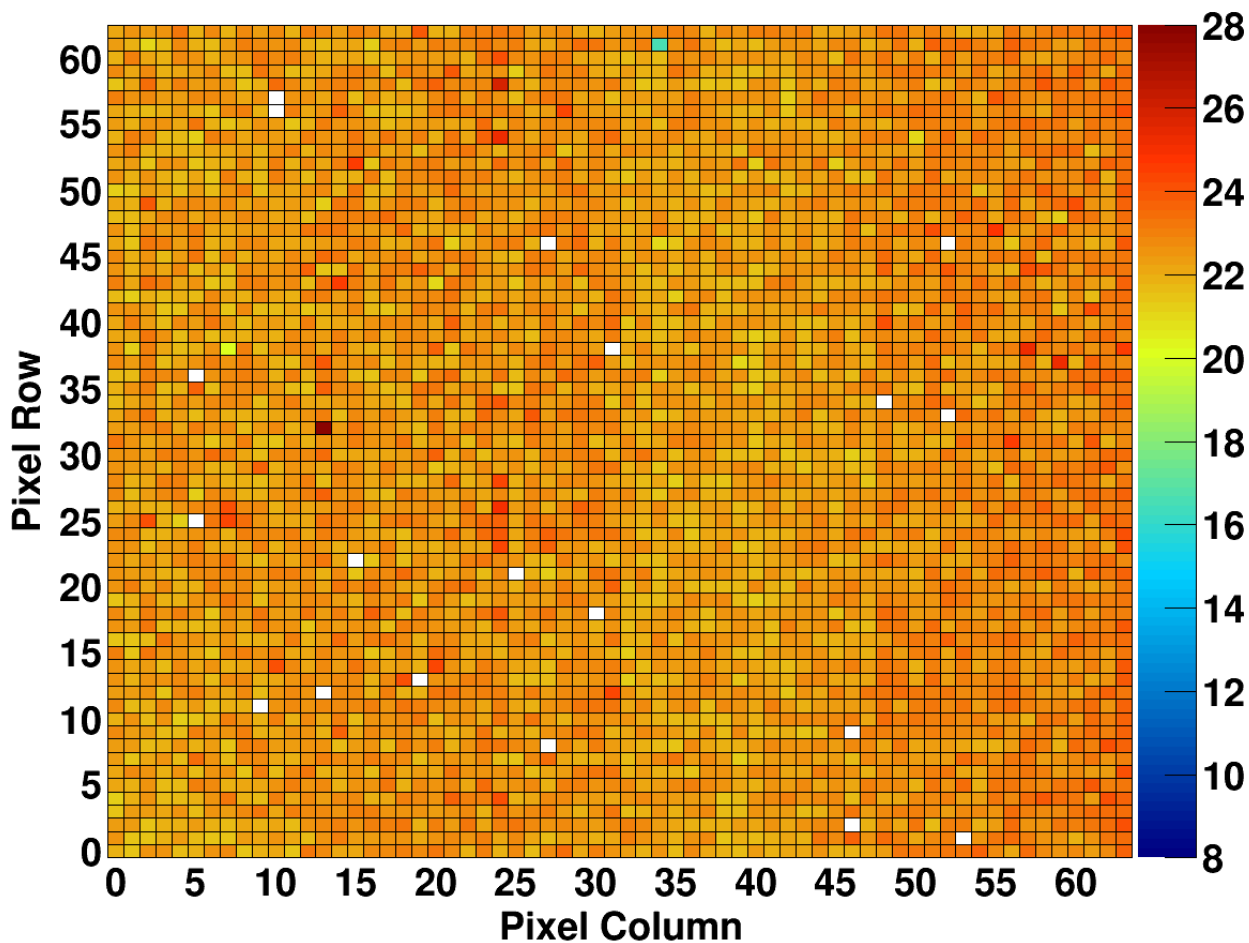
- Mo 17keV
- Chip SCM010 -> [Coolable assembly](#)
- Temperature: **20°C**
- Chip Running @10MHz for photon measurements (Less Measurement Time)
- Integration Time: 20 μ s
- CDS gain HIGH and LOW
- Noise and baseline acquired with 200ns Integration Time (Chip operated @40MHz)
- Depletion Voltage: 250V
- Biasing: Internal (results not affected by choosing INT or EXT)



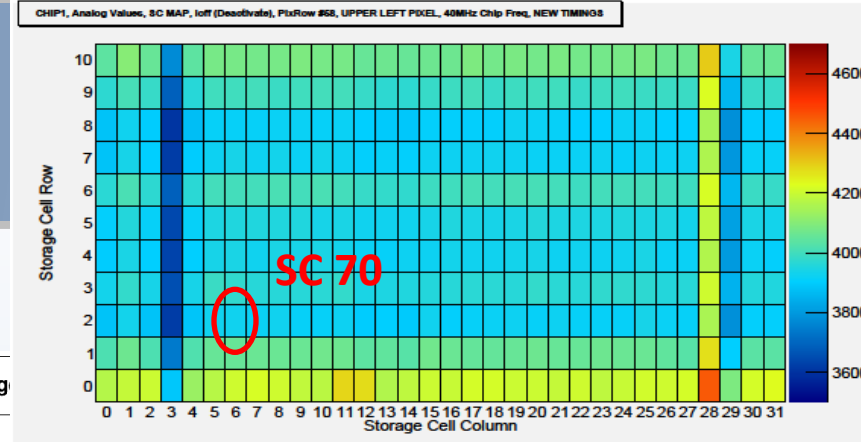
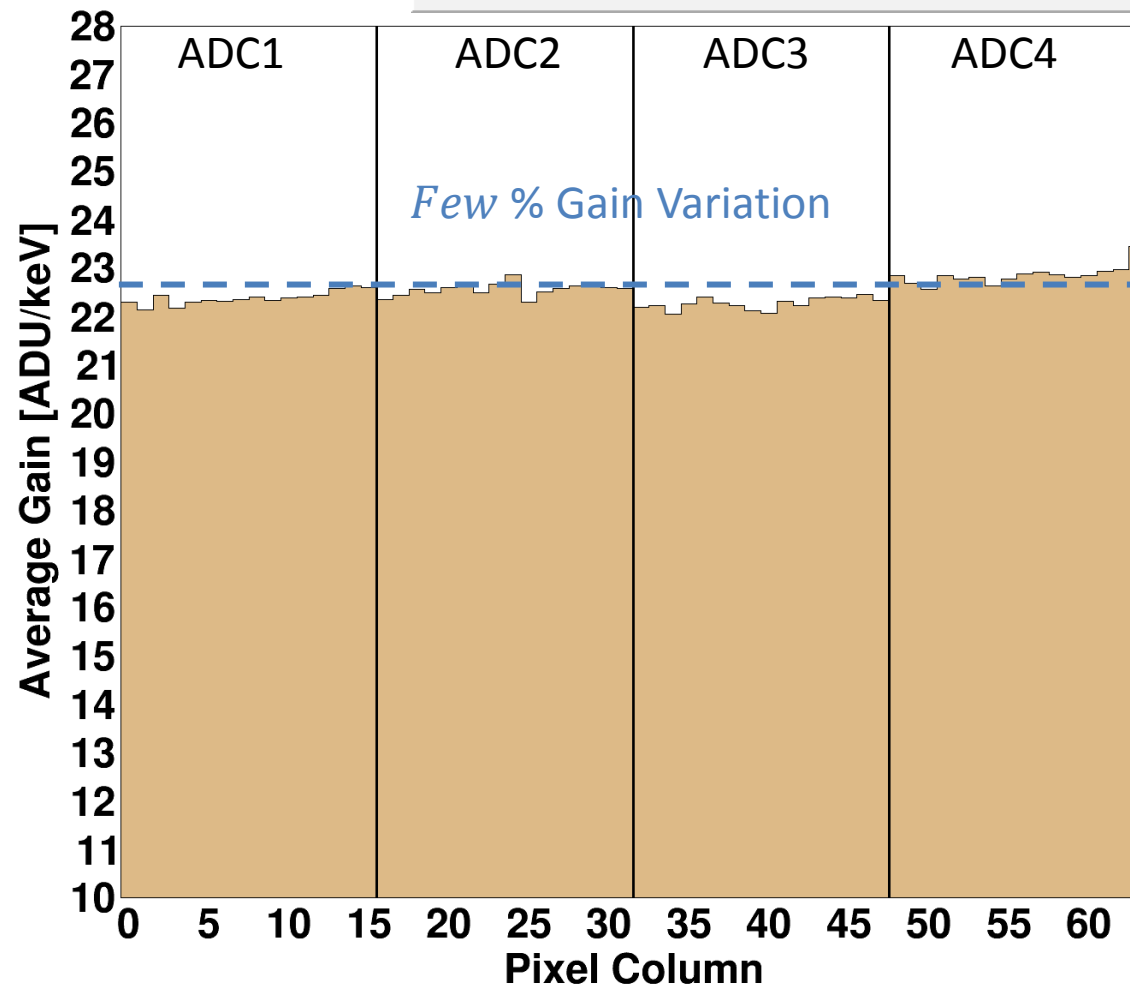
Gain MAP, Chip SCM 010

SC70, Vrefcds=650mV, CDS gain HIGH, Int_time = 20us

Gain Map, CDS Gain HIGH, 1 Mo Peak, SC 70, Vrefcds = 650mV, 10 MHz



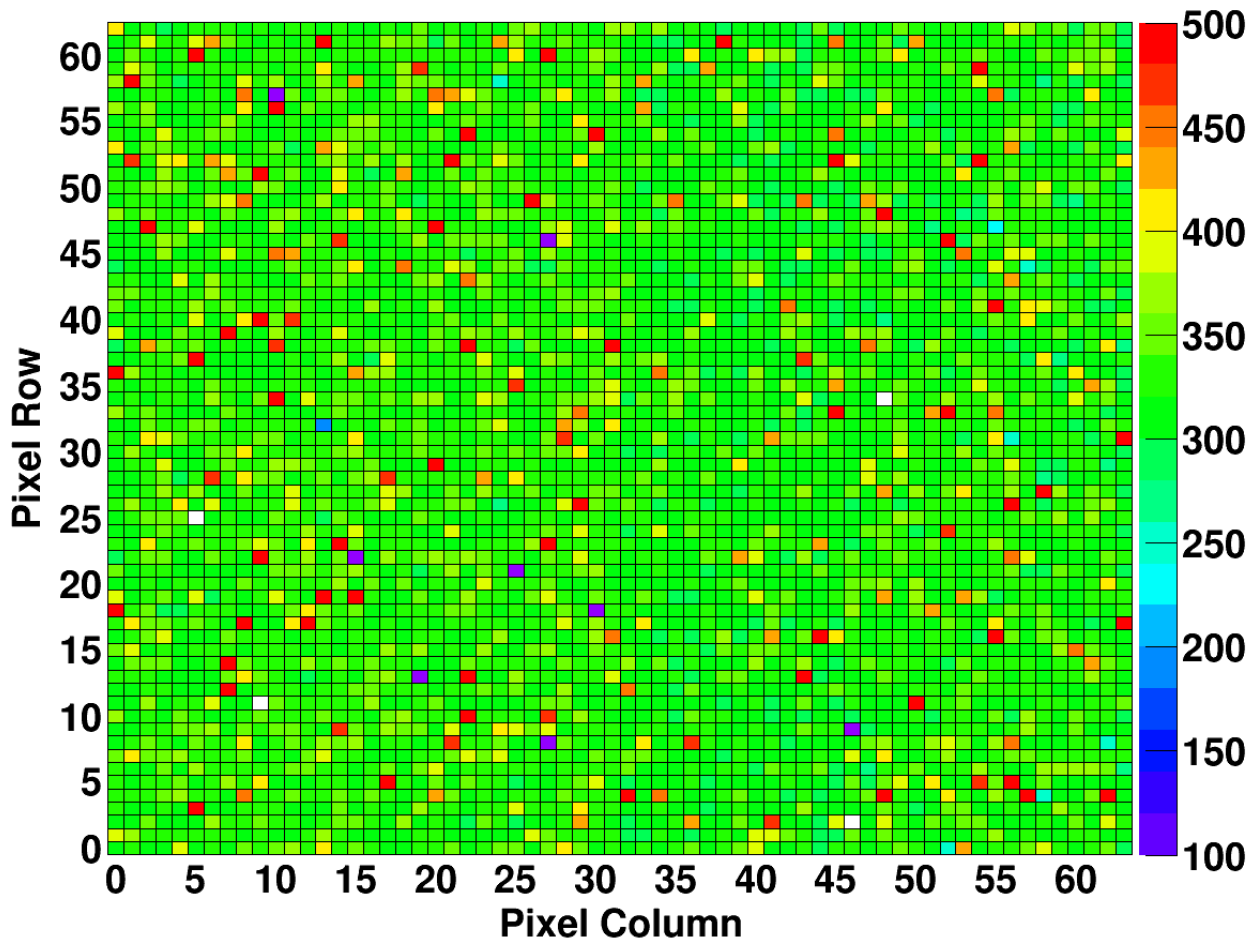
Average Gain, CDS Gain HIGH, Storage



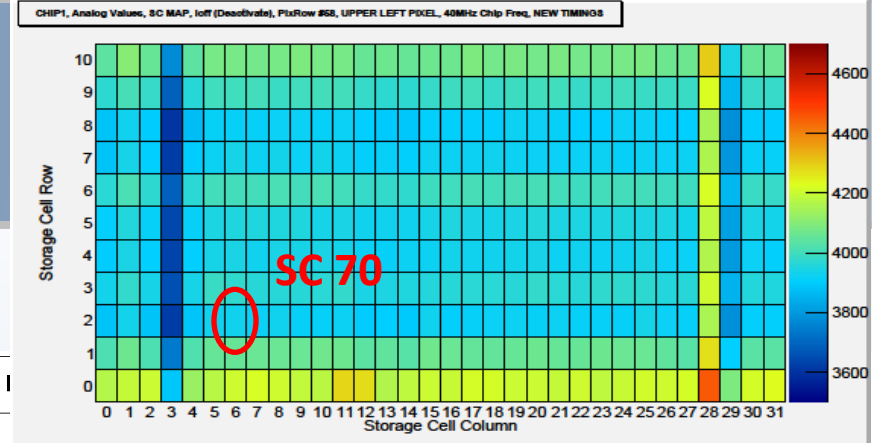
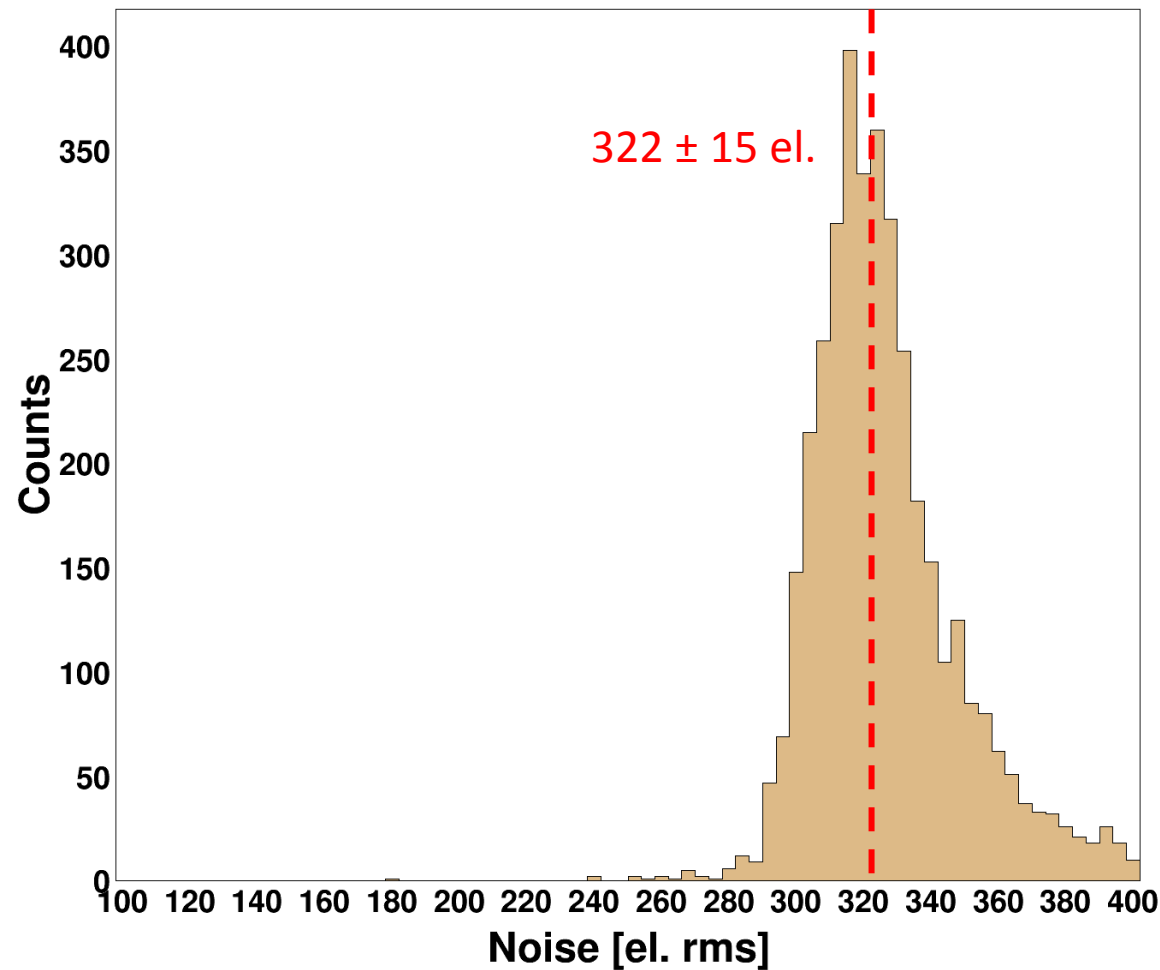
Noise MAP, Chip SCM 010

SC70, Vrefcads=650mV, CDS gain LOW, Int_time = 200ns

Noise Map, 200ns, CDS Gain LOW, SC 70, CHIP SCM010



Noise Distribution, CDS Gain LOW, I





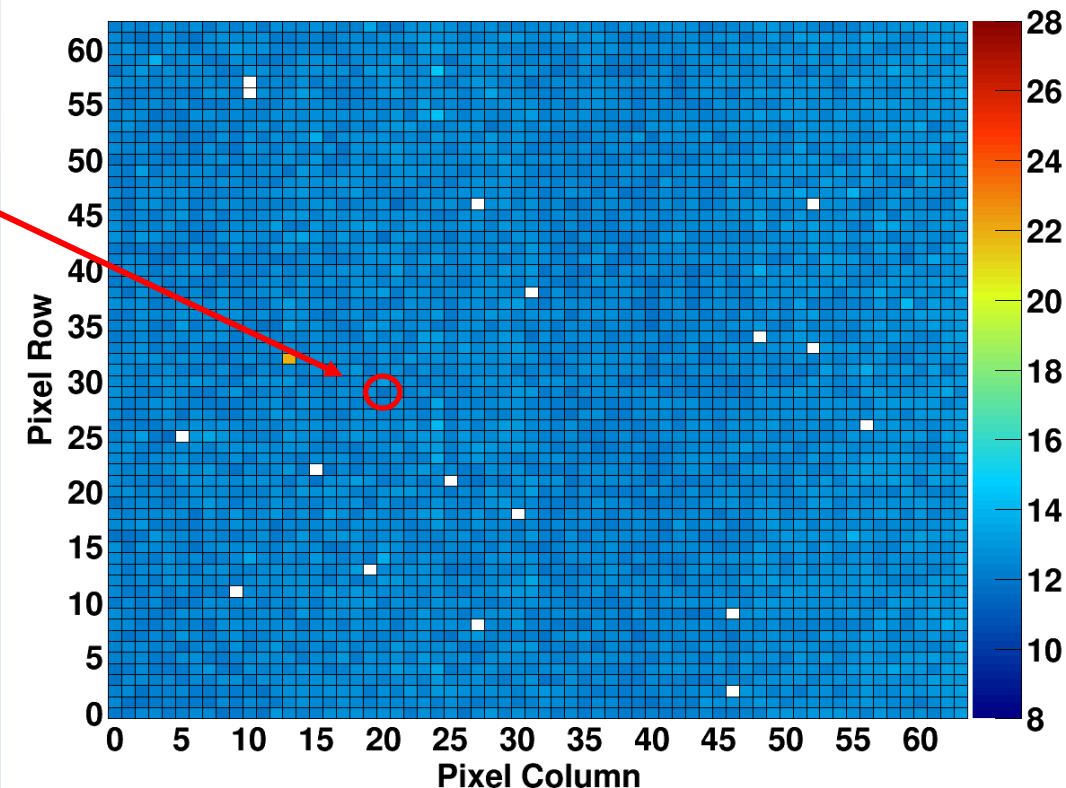
2

DR Scan / Linearity / Noise

DYNAMIC RANGE: MEASUREMENT CONDITIONS

- Chip SCM010 -> [Coolable assembly](#)
- Pixel 1565: Row 29, Second ADC from the pads
- SC70
- Infrared Laser: $\lambda=1030\text{nm}$
- Temperature: 20°C
- Chip Running @40MHz
- CDS gain HIGH and LOW
- Depletion Voltage: 250V
- Each point -> Average over 1000 frames
- Biasing: Internal

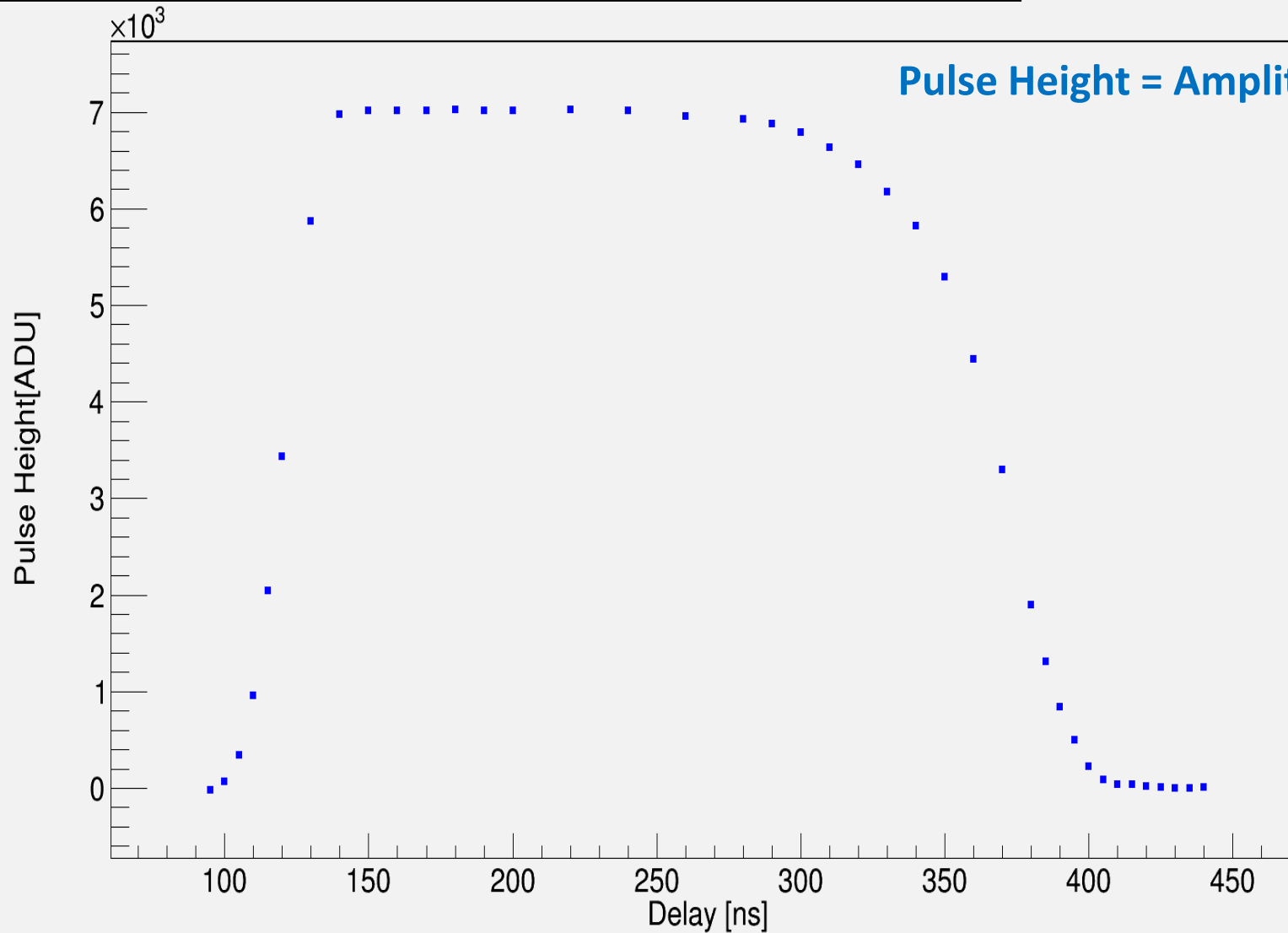
Gain Map, CDS Gain LOW, 1 Mo Peak, SC 70, Vrefcfs = 650mV, 10 MHz



DELAY SCAN



Delay Scan, CDS gain HIGH, System in the HIGH GAIN

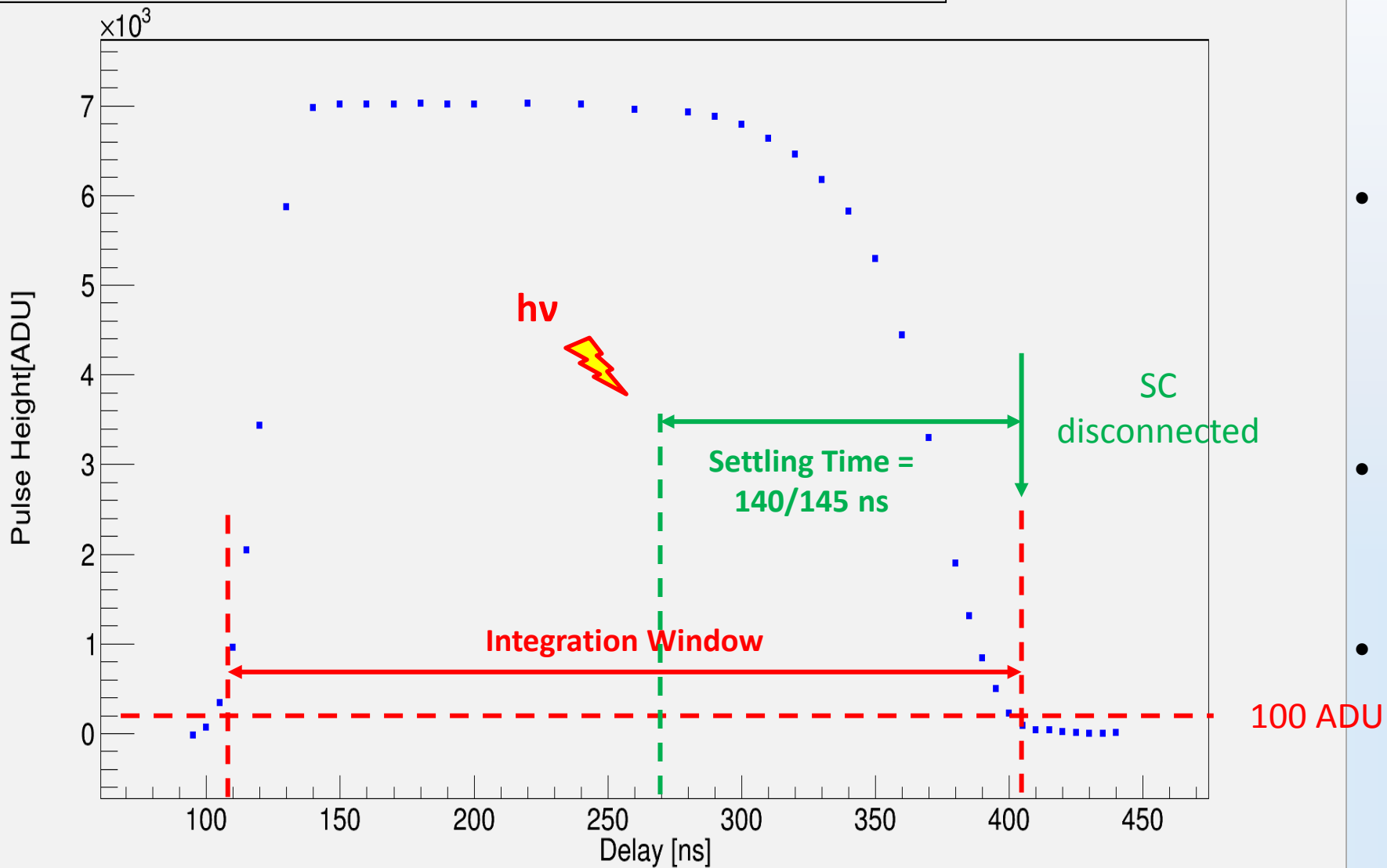


- Determination of the integration window: $PH \leq 100$ ADU assumed to be start and stop of the integration window.
- Assuming the last point as the SC disconnection.
- Take 140ns as “safe” settling time.

DELAY SCAN



Delay Scan, CDS gain HIGH, System in the HIGH GAIN

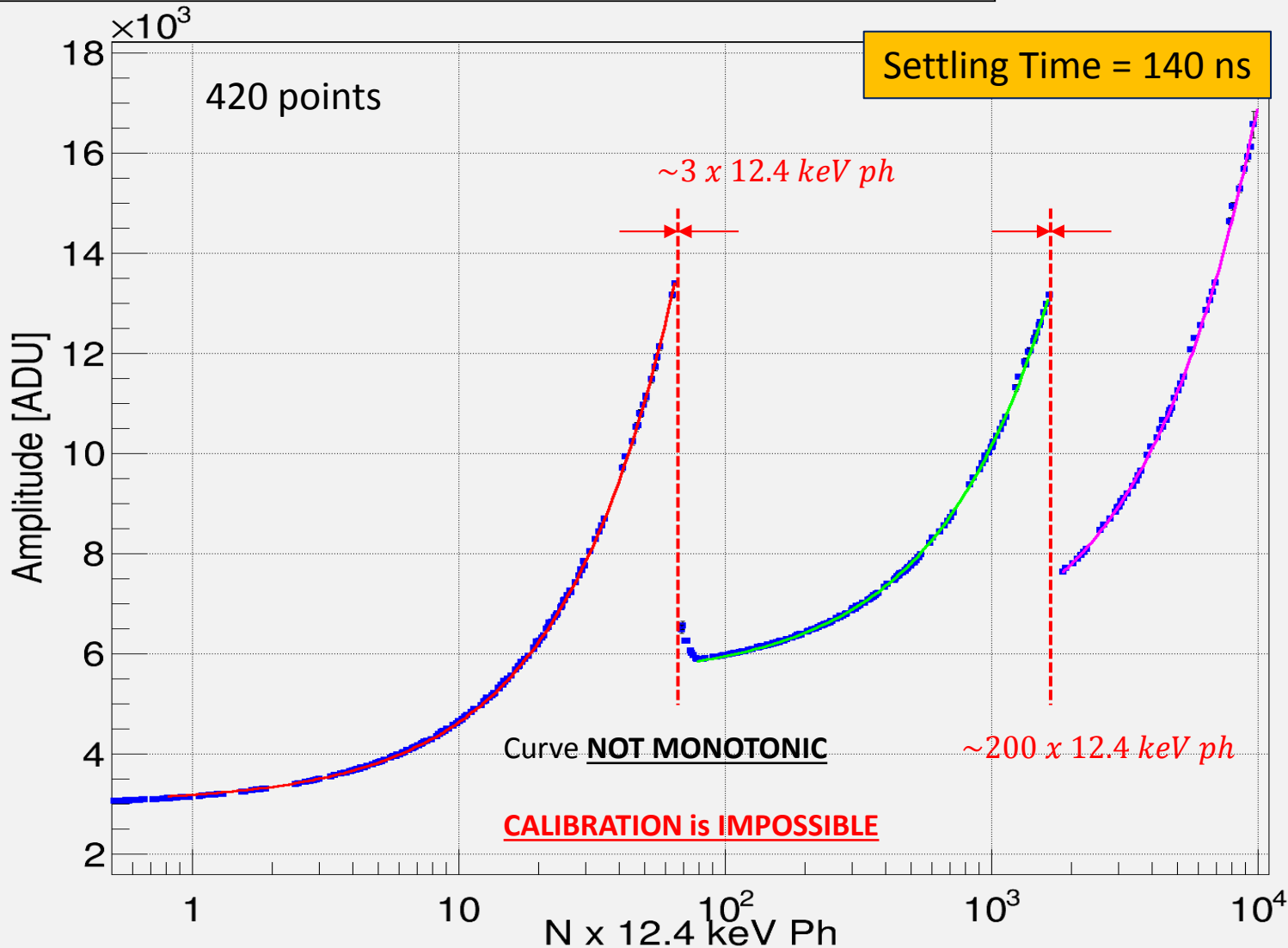


- Determination of the integration window: $PH \leq 100$ ADU assumed to be start and stop of the integration window.
- Assuming the last point as the SC disconnection.
- Take 140ns as “safe” settling time.

DR Scan - CDS gain LOW



Dynamic Range, CDS LOW, IR Laser, Settling time = 140 ns, Chip SCM010, Vrefcds = 650 mV, T = 20C



Data from analysis

Gain Switching HIGH-MEDIUM: $65.4 \times 12.4 \text{ keV ph}$.
Gap HIGH-MEDIUM: ca. $3 \times 12.4 \text{ keV ph}$.

Gain Switching Medium-LOW: ca. $1650 \times 12.4 \text{ keV ph}$.
Gap Medium-LOW: ca. $200 \times 12.4 \text{ keV ph}$.

Last point in LOW gain: ca. $9650 \times 12.4 \text{ keV ph}$.

Gains obtained from the fit:

HIGH GAIN = 12.94 ADU/keV

MEDIUM GAIN = 0.375 ADU/keV

LOW GAIN = 0.092 ADU/keV

Theoretical Ratios:

$$\begin{cases}
 C_{\text{HIGH}} = 60\text{fF} \\
 C_{\text{MEDIUM}} = 3\text{pF} \\
 C_{\text{LOW}} = 10\text{pF}
 \end{cases}
 \begin{cases}
 \frac{HG}{MG} = \frac{C_{\text{Medium}} + C_{\text{HIGH}}}{C_{\text{HIGH}}} = 51 \\
 \frac{MG}{LG} \cong \frac{C_{\text{Medium}} + C_{\text{LOW}} + C_{\text{HIGH}}}{C_{\text{Medium}} + C_{\text{HIGH}}} = 4.27
 \end{cases}$$

Ratios from fit:

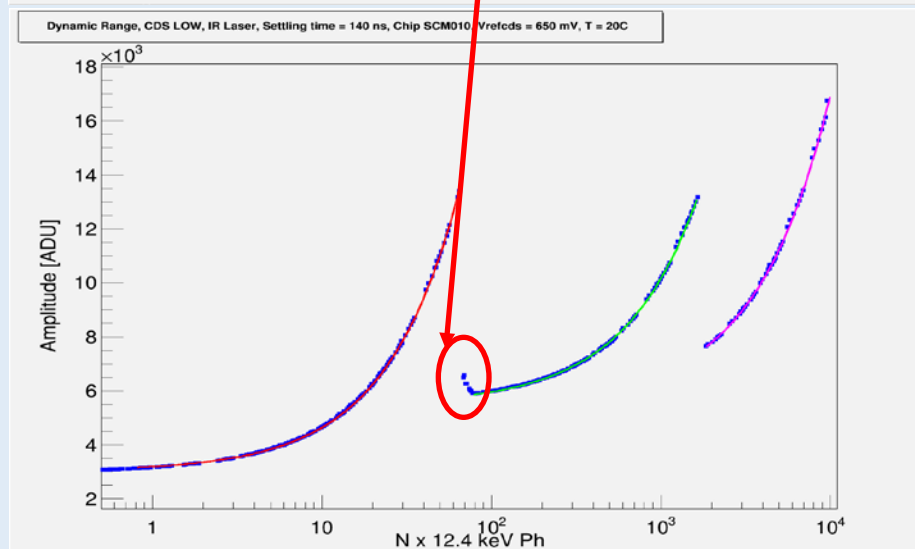
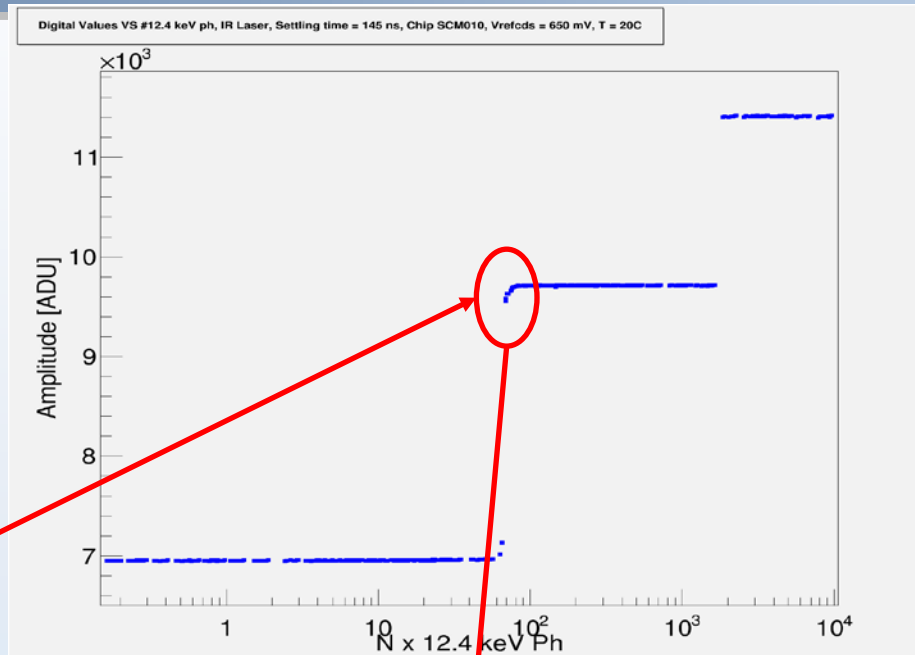
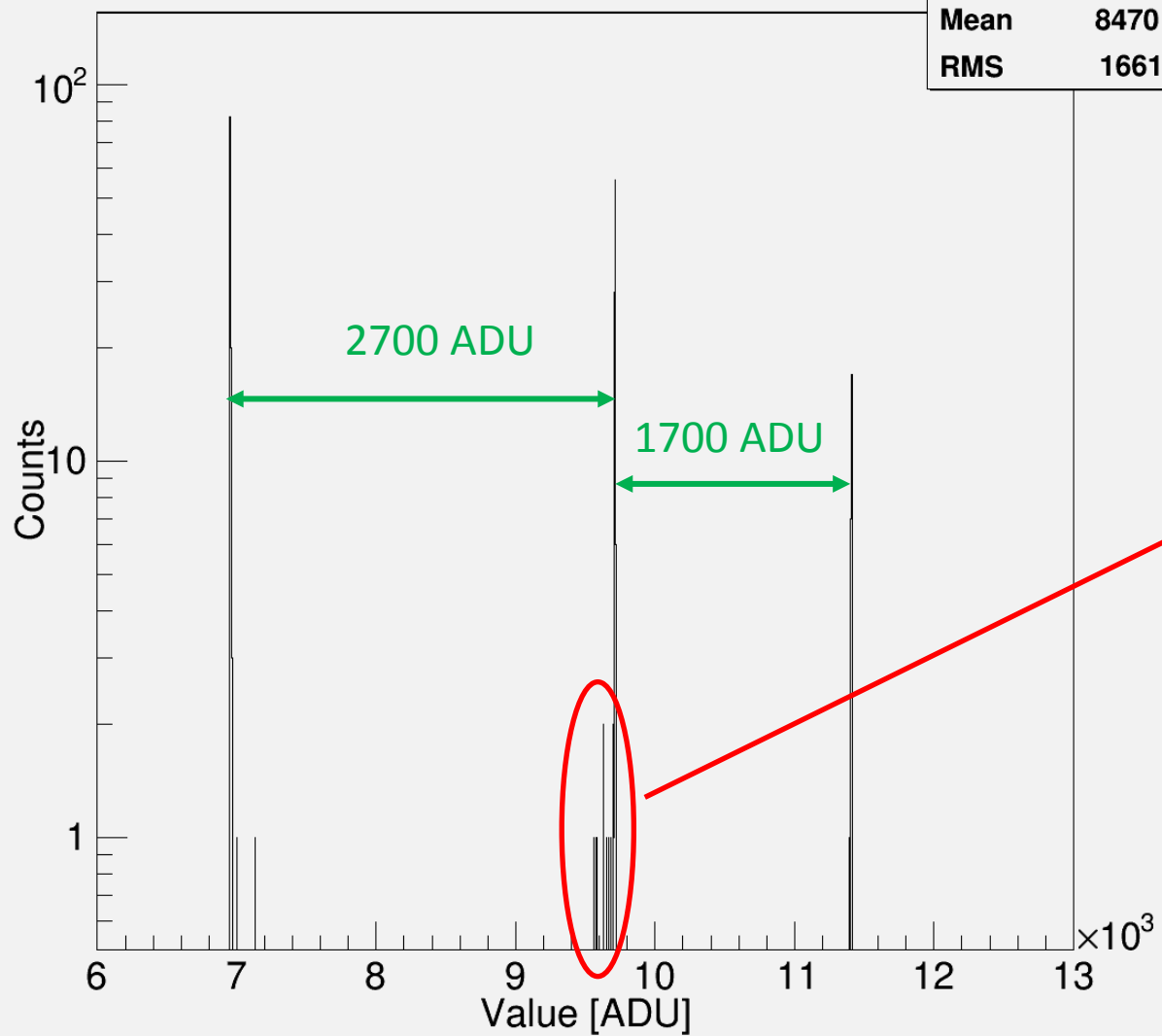
HG/MG = 34.5 (parasitic dominant)

MG/LG = 4.1

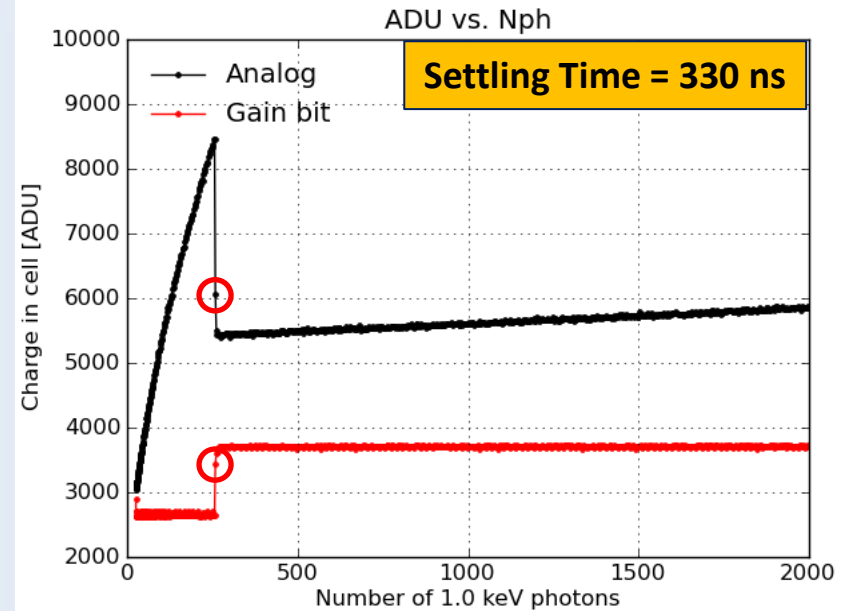
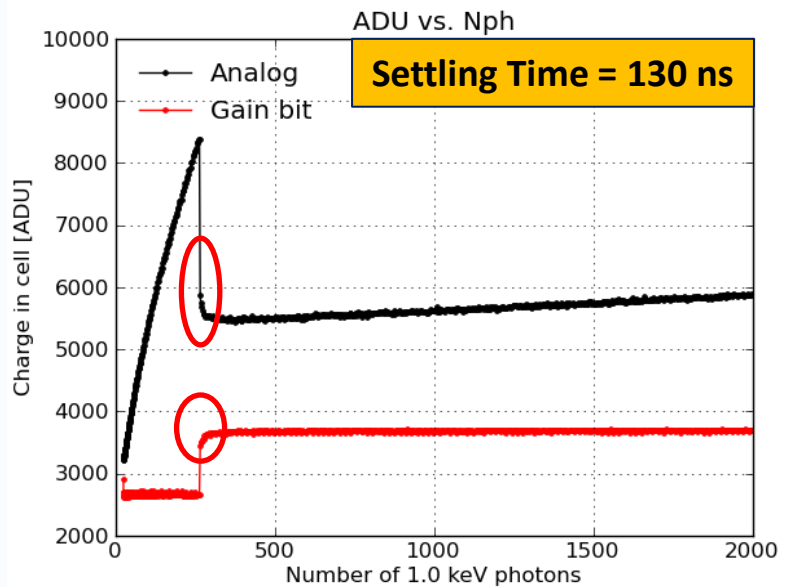
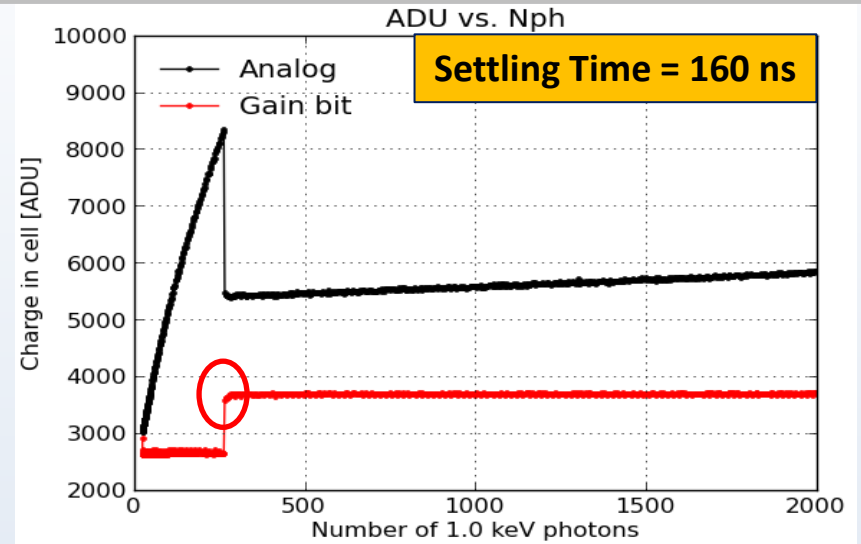
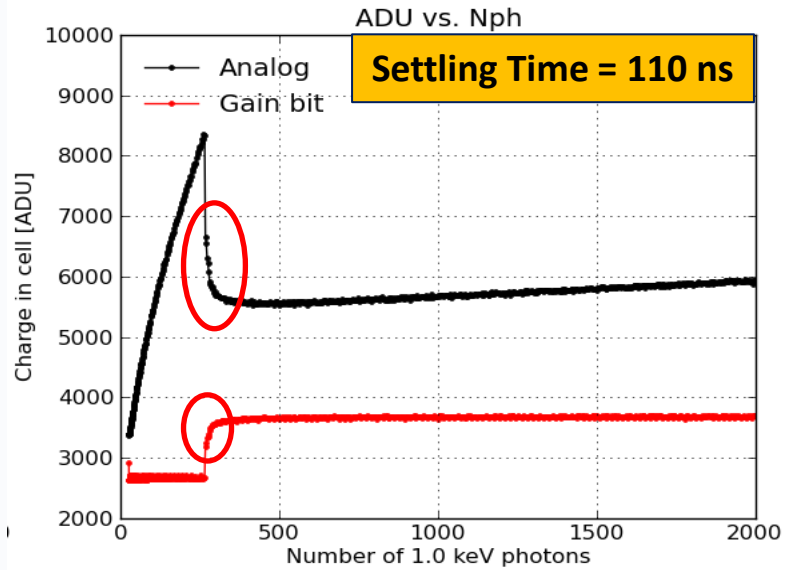
DR Scan - CDS gain LOW - Digital



Digital Values



DR Scan – Pulsed Capacitor Module



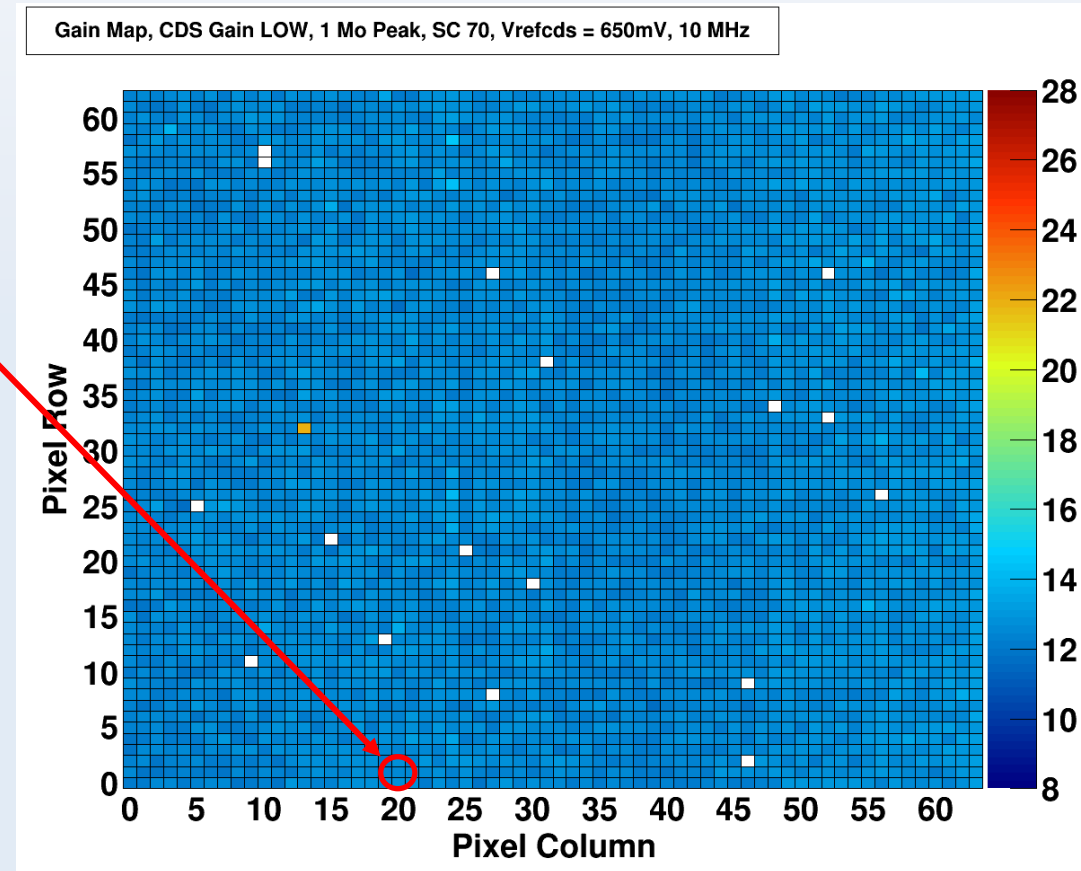
DYNAMIC RANGE



DYNAMIC RANGE: TRIALS...

- Chip 1 -> No Cooling (Chip Temp ~60/70 °C)
- Pixel Row 2, Second ADC from the pads
- SC 70, SC 100
- CDS gain HIGH and LOW
- Old Readout Scheme
- Different Settling Times
- Different comparator currents
- And so on....

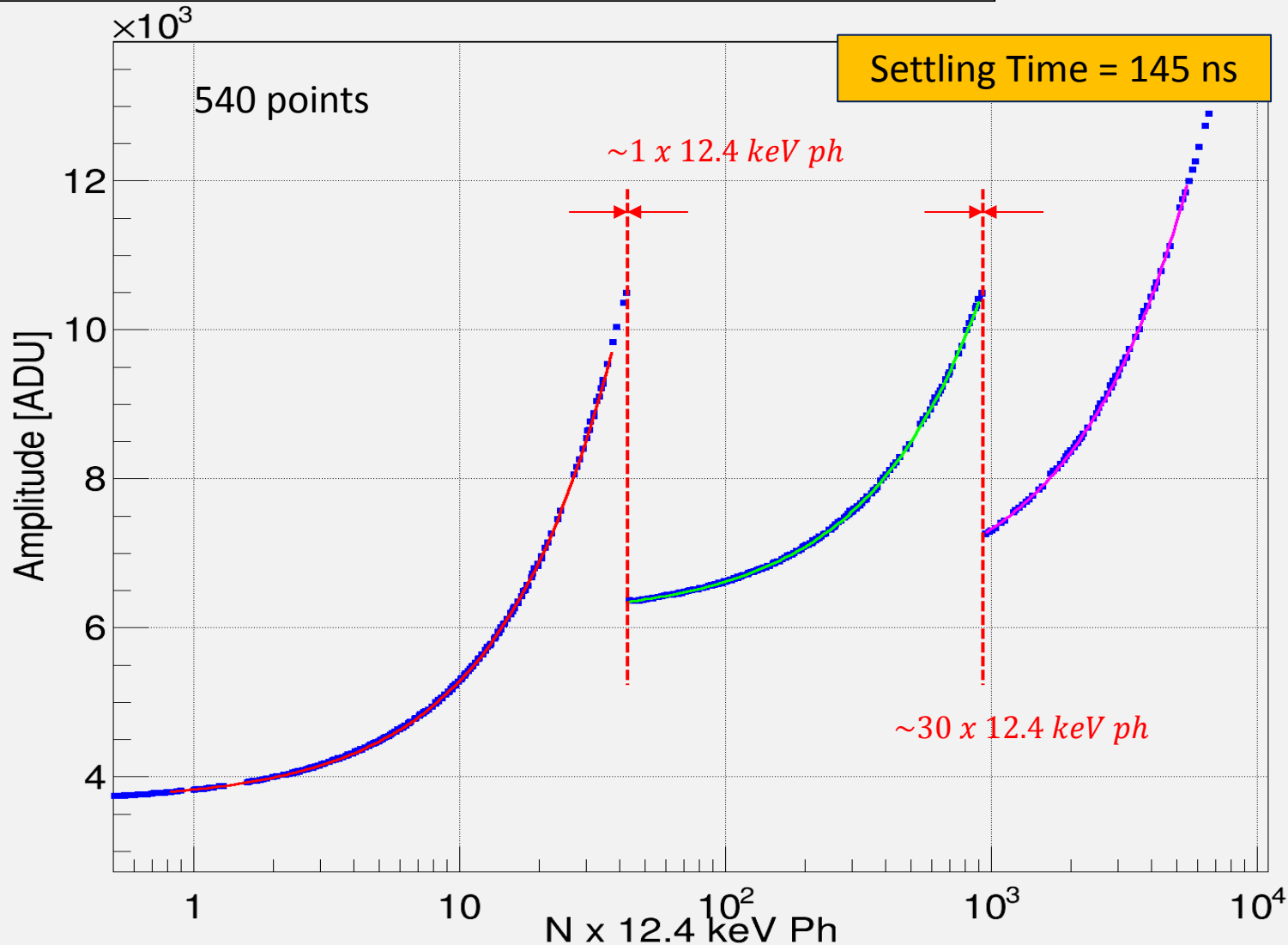
The non linearity problem wasn't solved...



DR Scan - CDS gain LOW



Dynamic Range, CDS LOW, IR Laser, Settling time = 145 ns, Chip 1, Vrefcads = 650 mV, No Cooling



Data from analysis

Gain Switching HIGH-MEDIUM: 42.5 x 12.4 keV ph.
Gap HIGH-MEDIUM: ca. 1 x 12.4 keV ph.

Gain Switching Medium-LOW: ca. 925 x 12.4 keV ph.
Gap Medium-LOW: ca. 30 x 12.4 keV ph.

Last point in LOW gain: ca. 6600 x 12.4 keV ph.

Gains obtained from the fit:

HIGH GAIN = 13.02 ADU/keV
MEDIUM GAIN = 0.38 ADU/keV
LOW GAIN = 0.083 ADU/keV

Theoretical Ratios:

$$\begin{cases}
 C_{\text{HIGH}} = 60\text{fF} \\
 C_{\text{MEDIUM}} = 3\text{pF} \\
 C_{\text{LOW}} = 10\text{pF}
 \end{cases}
 \begin{cases}
 \frac{HG}{MG} = \frac{C_{\text{MEDIUM}} + C_{\text{HIGH}}}{C_{\text{HIGH}}} = 51 \\
 \frac{MG}{LG} \cong \frac{C_{\text{MEDIUM}} + C_{\text{LOW}} + C_{\text{HIGH}}}{C_{\text{MEDIUM}} + C_{\text{HIGH}}} = 4.27
 \end{cases}$$

Ratios from fit:

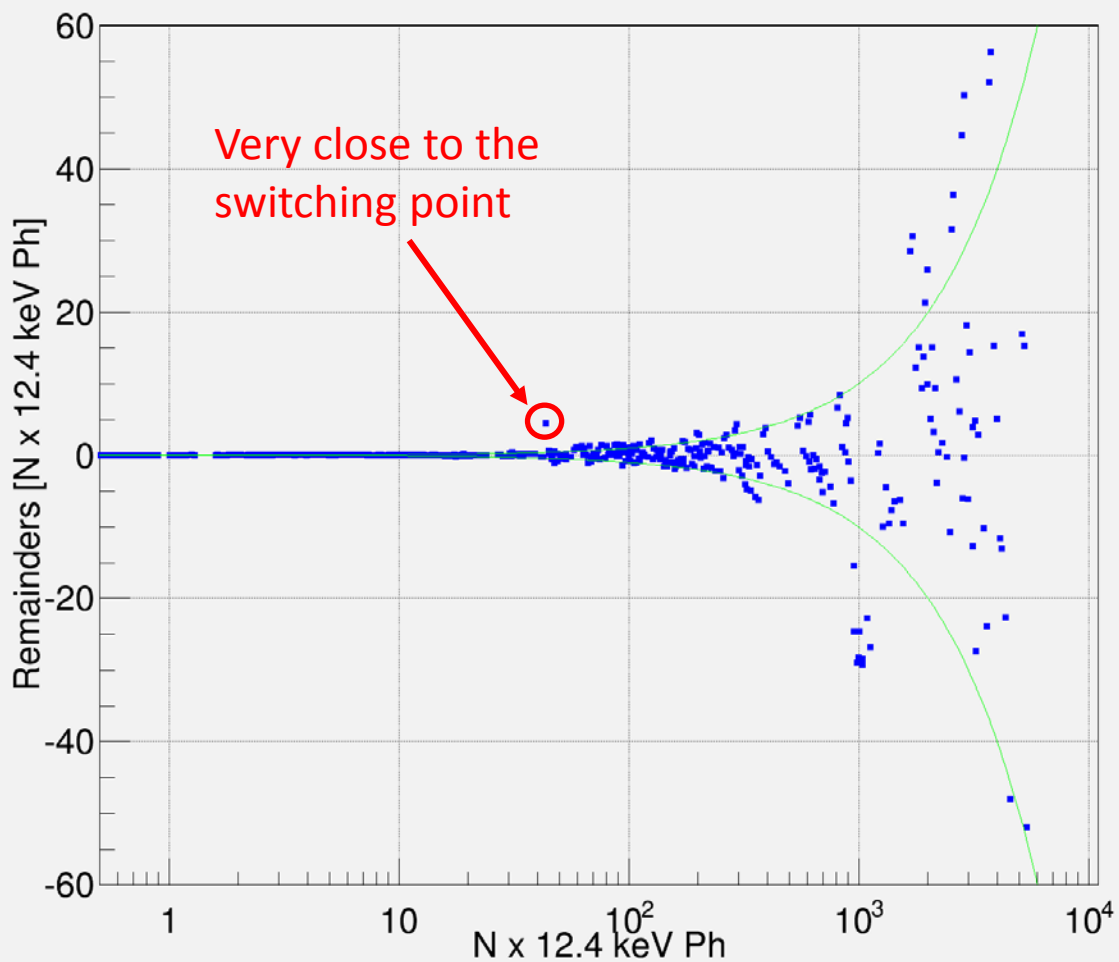
HG/MG = 34.26 (parasitic dominant)
MG/LG = 4.55

Linearity & Noise over DR - CDS gain LOW



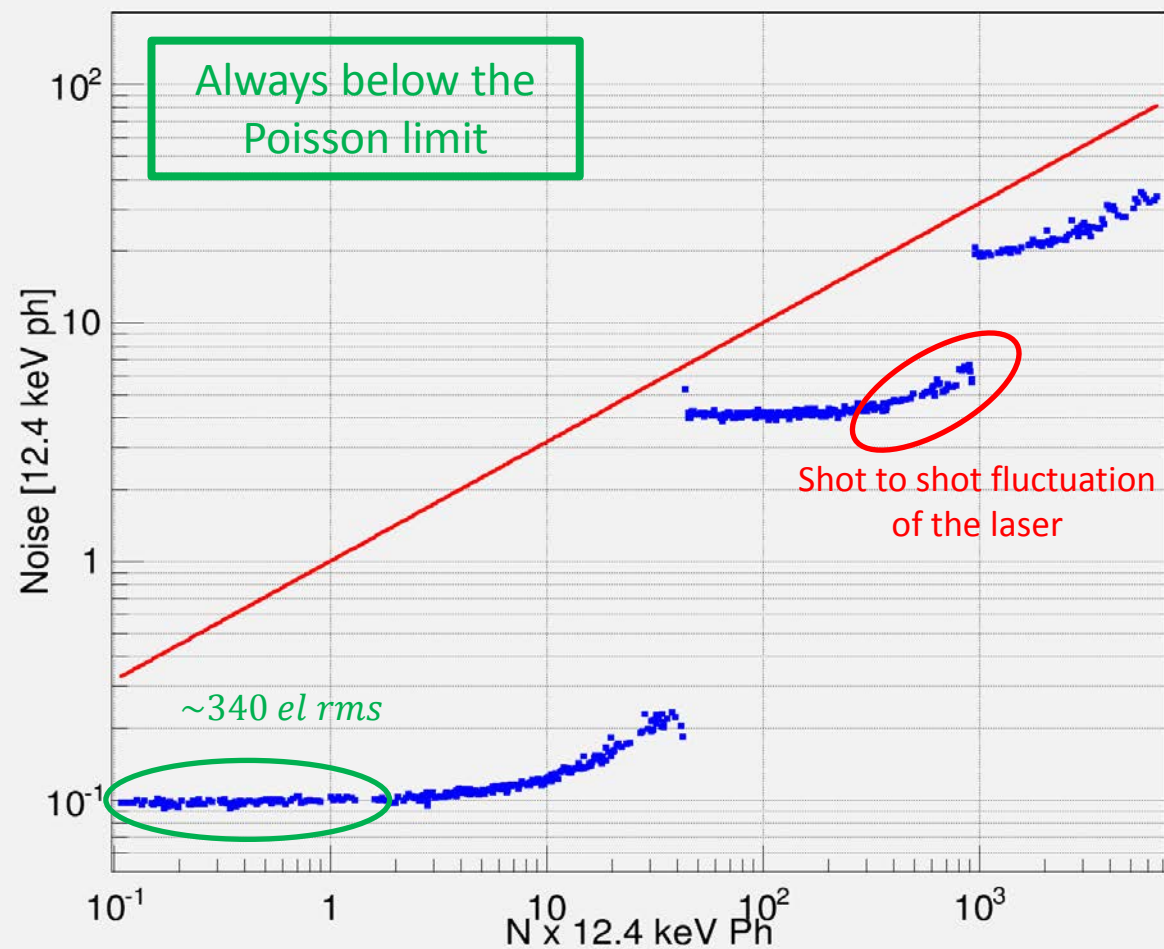
±1%

Remainders, IR Laser, Settling time = 145 ns, Chip 1, Vrefcads = 650 mV, No Cooling



Poisson Limit

Noise Over Dynamic Range, IR Laser, Settling time = 145 ns, Chip 1, Vrefcads = 650 mV, No Cooling



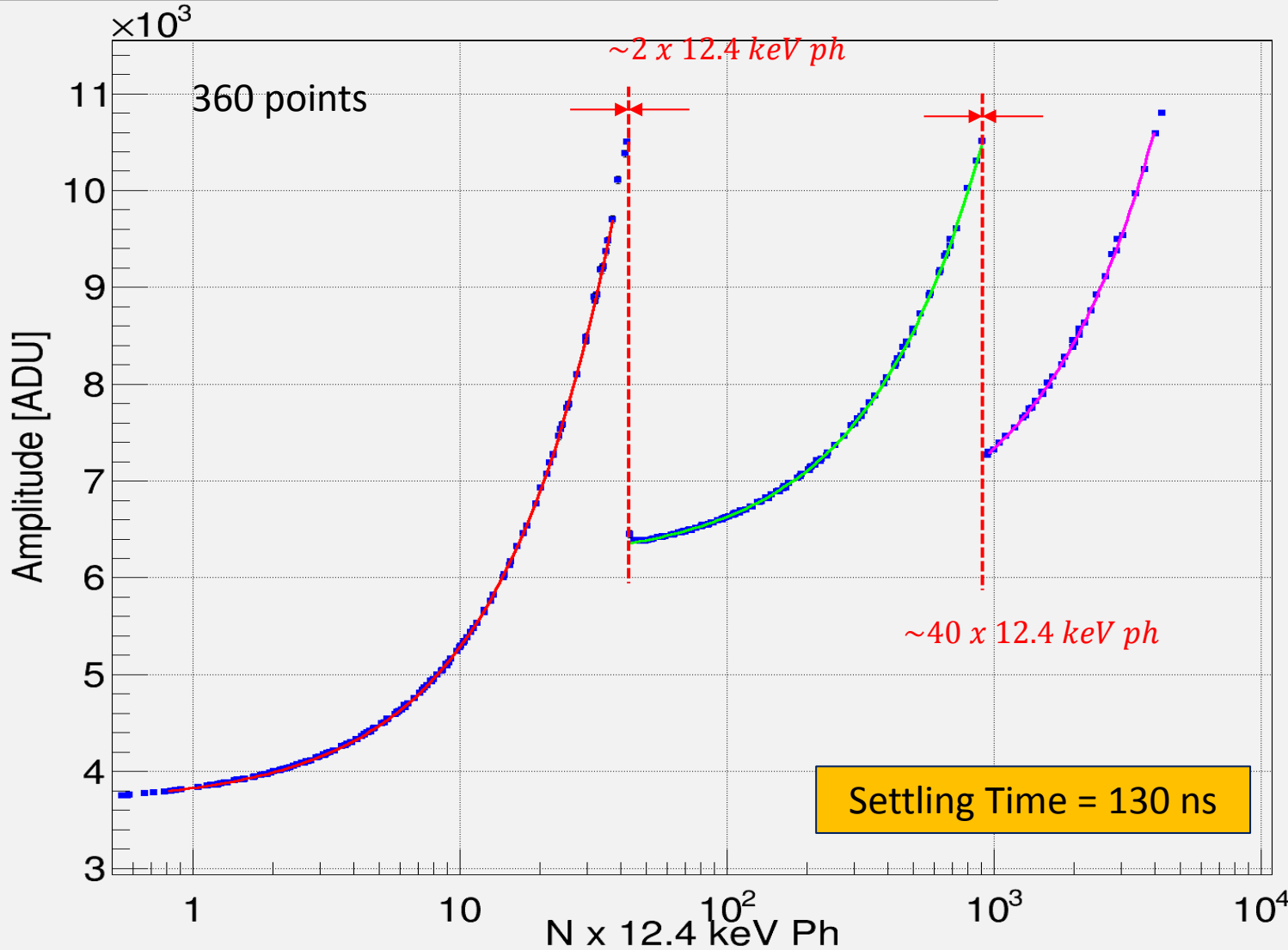


**Going back from this point to
Settling Time 130 ns**

DR Scan - CDS gain LOW



Dynamic Range, CDS LOW, IR Laser, Settling time = 130 ns, Chip 1, Vrefc ds = 650 mV, No Cooling



Data from analysis

Gain Switching HIGH-MEDIUM: $\times 12.4$ keV ph.
Gap HIGH-MEDIUM: ca. 1×12.4 keV ph.

Gain Switching Medium-LOW: ca. 900×12.4 keV ph.
Gap Medium-LOW: ca. 40×12.4 keV ph.

Last point in LOW gain: ca. 4250×12.4 keV ph.

Gains obtained from the fit:

HIGH GAIN = 13.1 ADU/keV
MEDIUM GAIN = 0.38 ADU/keV
LOW GAIN = 0.09 ADU/keV

Theoretical Ratios:

$$\begin{cases}
 C_{\text{HIGH}} = 60\text{fF} \\
 C_{\text{MEDIUM}} = 3\text{pF} \\
 C_{\text{LOW}} = 10\text{pF}
 \end{cases}
 \begin{cases}
 \frac{HG}{MG} = \frac{C_{\text{MEDIUM}} + C_{\text{HIGH}}}{C_{\text{HIGH}}} = 51 \\
 \frac{MG}{LG} \cong \frac{C_{\text{MEDIUM}} + C_{\text{LOW}} + C_{\text{HIGH}}}{C_{\text{MEDIUM}} + C_{\text{HIGH}}} = 4.27
 \end{cases}$$

Ratios from fit:

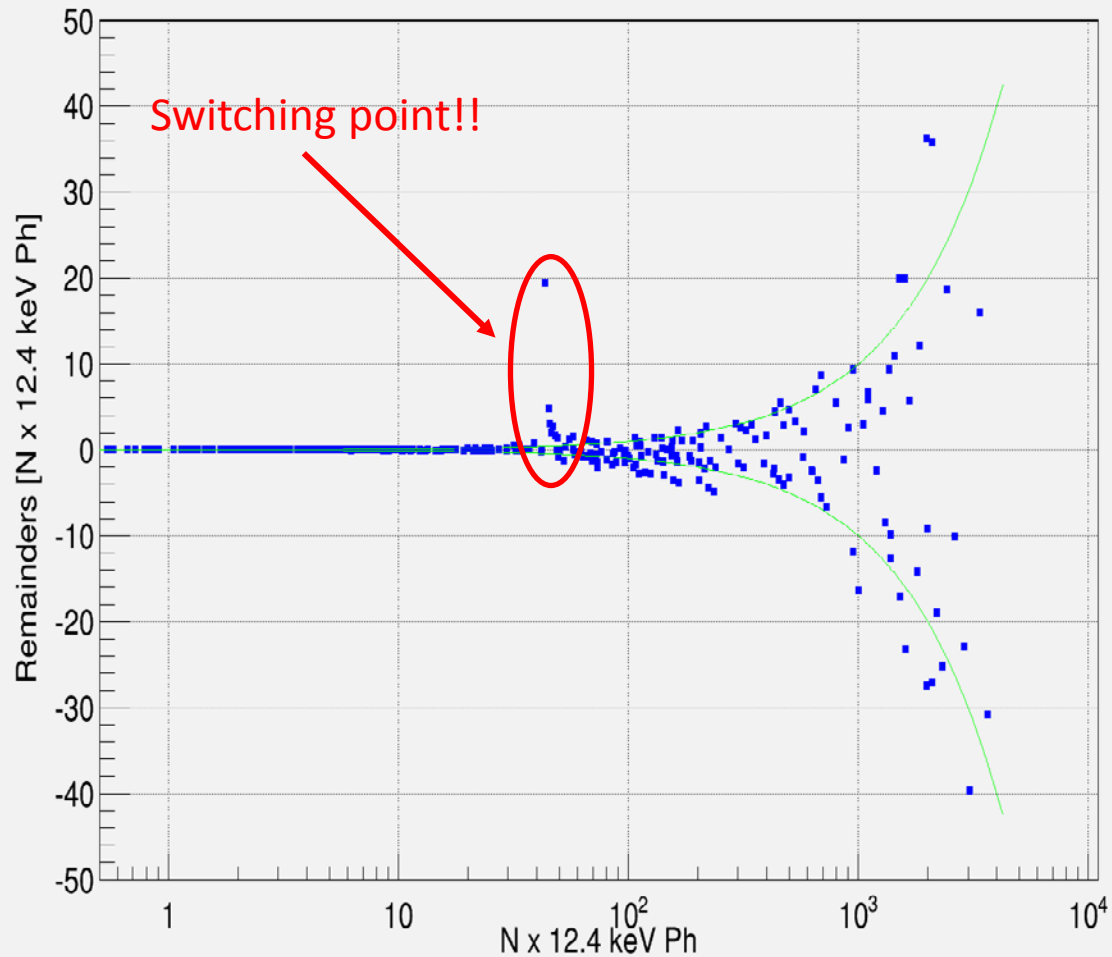
HG/MG = 33.6 (parasitic dominant)
MG/LG = 4.38

Linearity & Noise over DR - CDS gain LOW



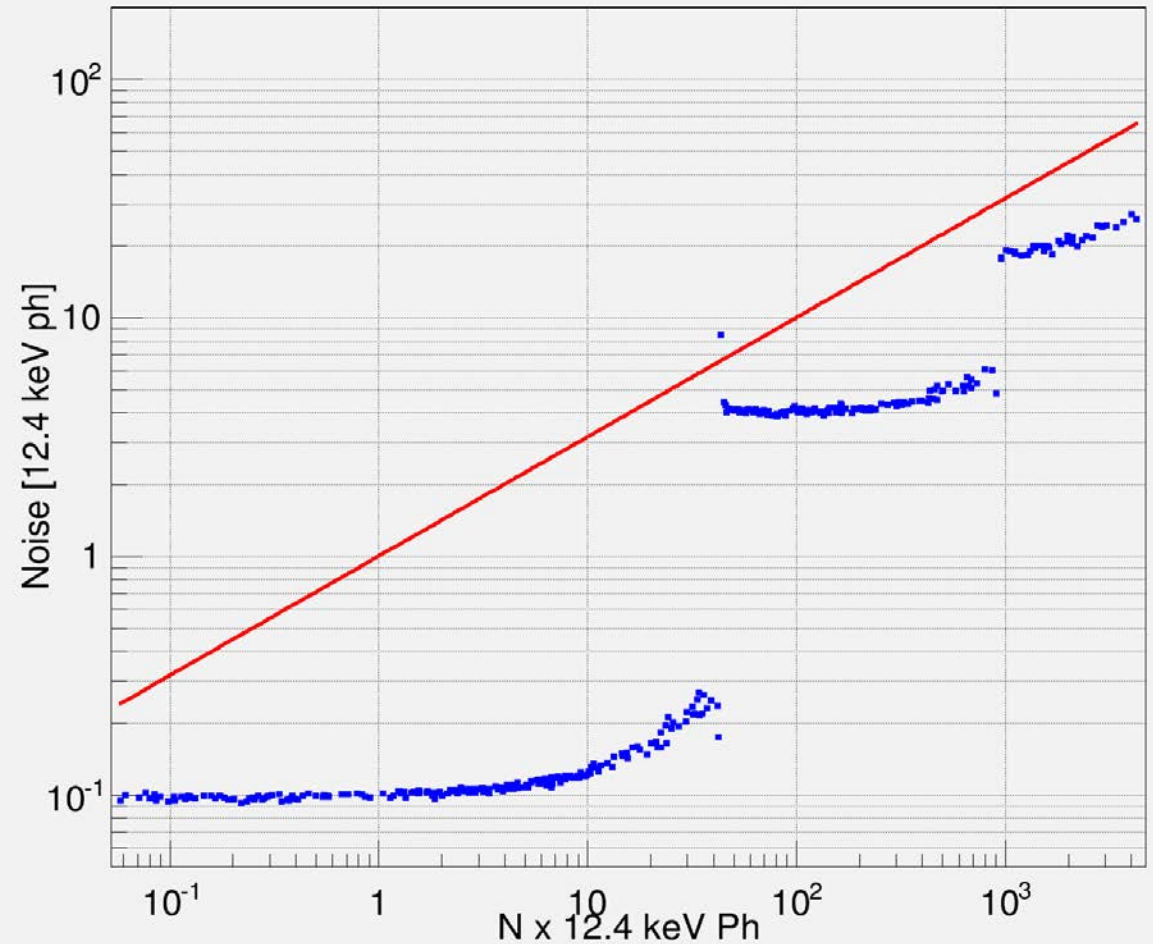
±1%

Remainders, IR Laser, Settling time = 145 ns, Chip 1, Vrefcfs = 650 mV, No Cooling



Poisson Limit

Noise Over Dynamic Range, IR Laser, Settling time = 145 ns, Chip 1, Vrefcfs = 650 mV, No Cooling





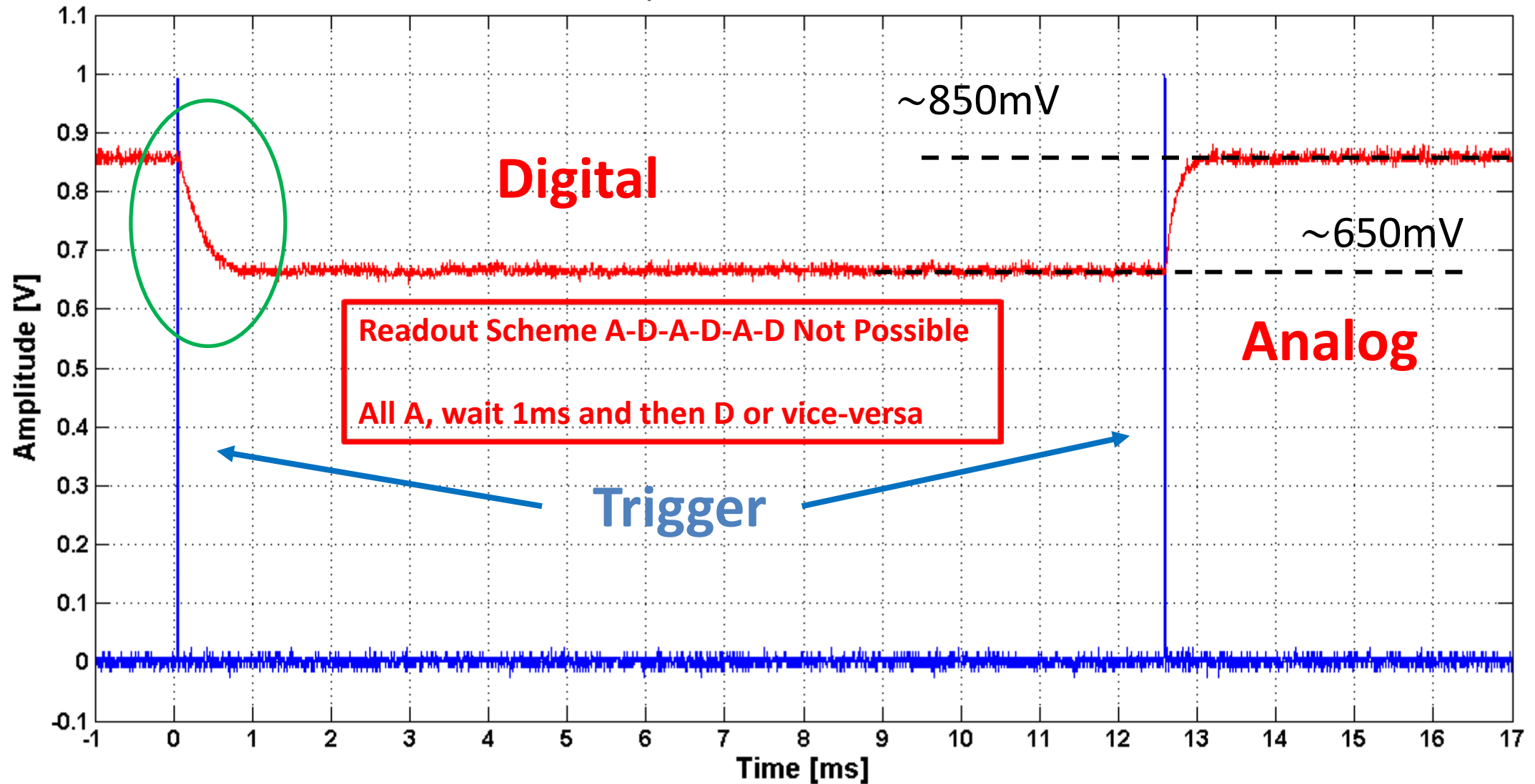
3

**Burst Mode – Problem of
Vrefpxb speed...**

Oscilloscope



Evolution of V_{refpxb} between Analog and Digital readout



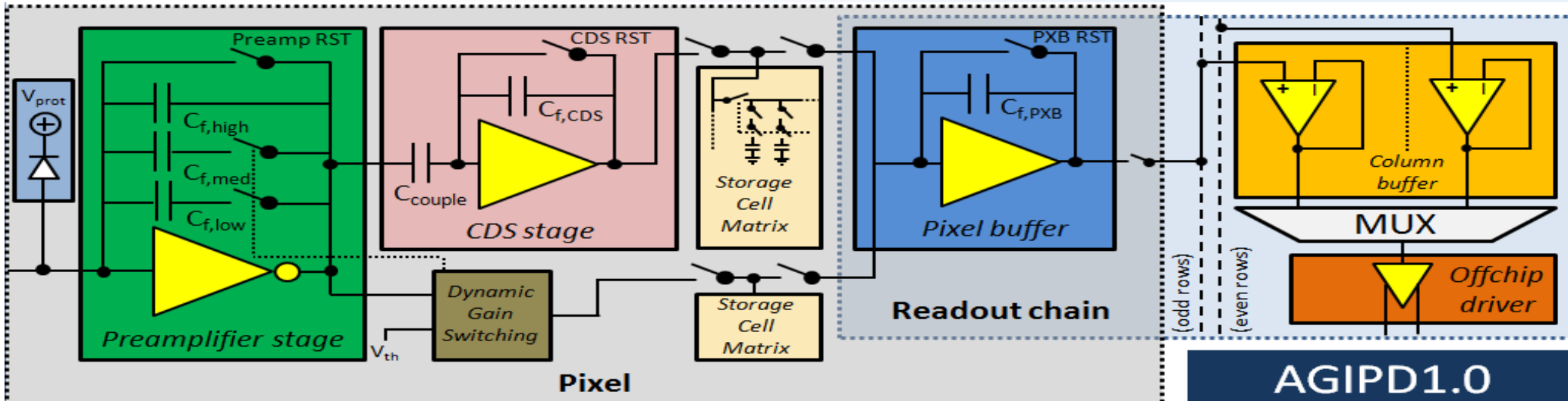


4

Droop

Measurement

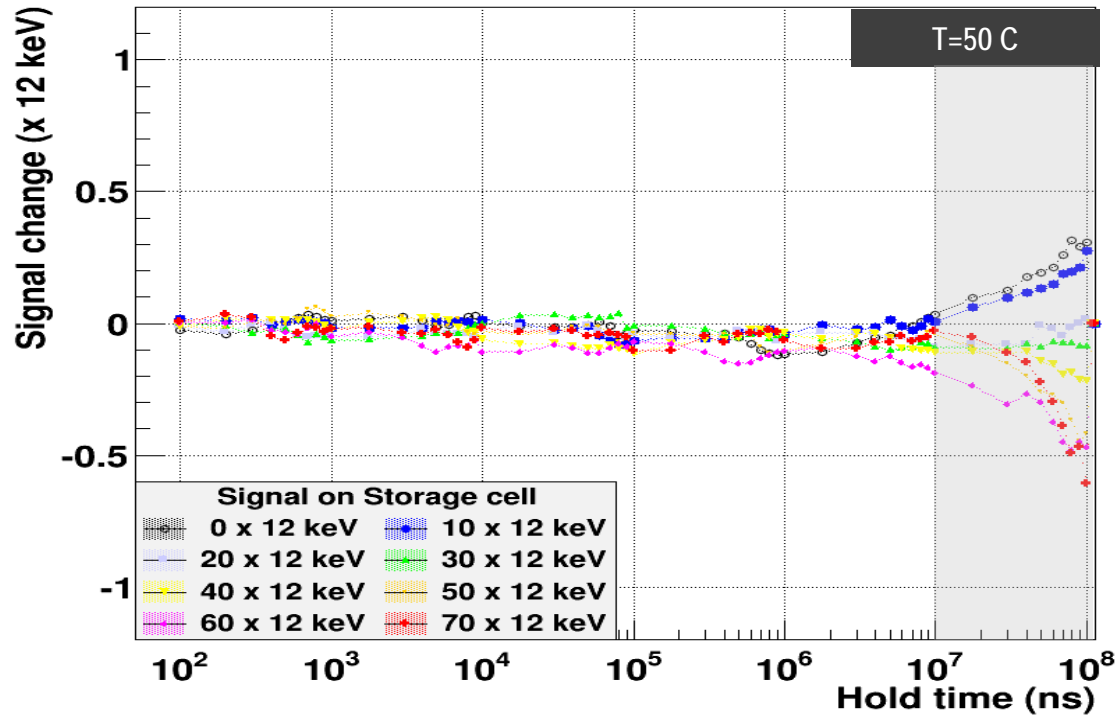
- After having changed the readout scheme, the ‚precharging‘ of the bus between Storage Cell and PXB is performed by the front end:
 - Analog Storage Cell Matrix: $V_{\text{ref,CDS}}$
 - Digital Storage Cell Matrix: Voltage from voltage divider
- Writing a virtual signal onto storage cell by increasing $V_{\text{ref,CDS}}$ and putting CDS buffer in reset
- Setting $V_{\text{ref,CDS}}$ back to baseline
- Putting chip into precharge mode (SETMEM)
- Waiting (up to 100 ms – EuXFEL cycle)
- Reading out
- Comparing value after waiting to value without additional hold time



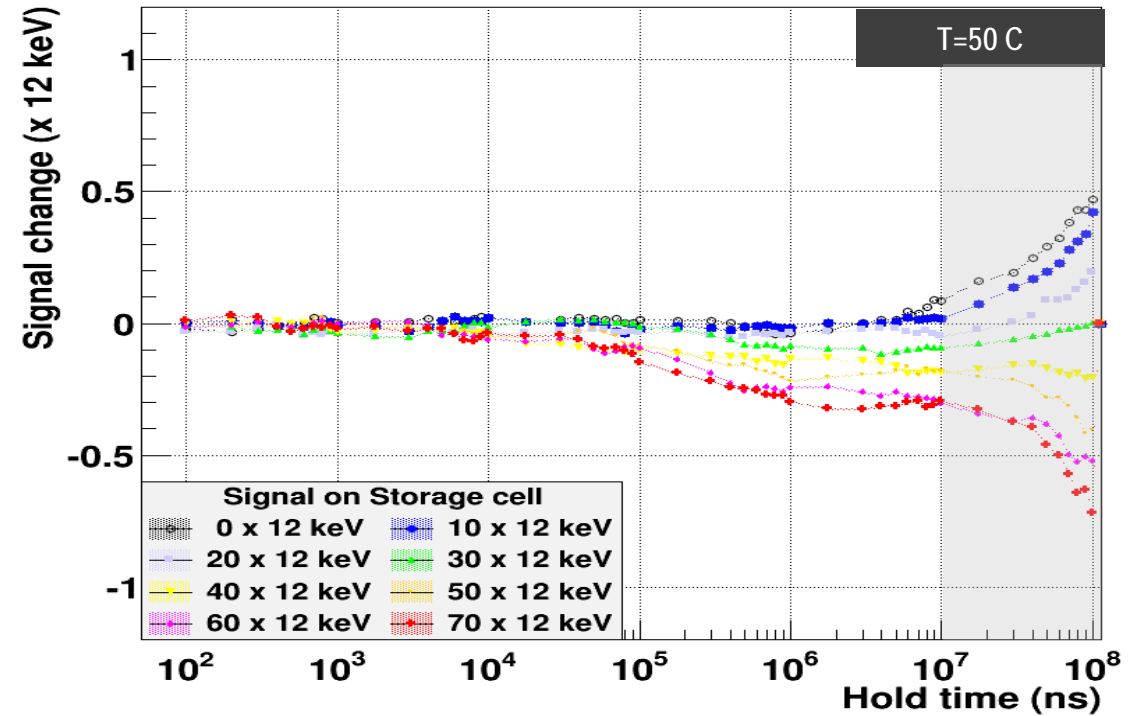
Droop of the analog Storage Cells (T=50 C)



Pixel 325 – Storage Cell 66 - Droop (x12 keV, CDS gain HIGH)



Pixel 1825 – Storage Cell 66 - Droop (x12 keV, CDS gain HIGH)

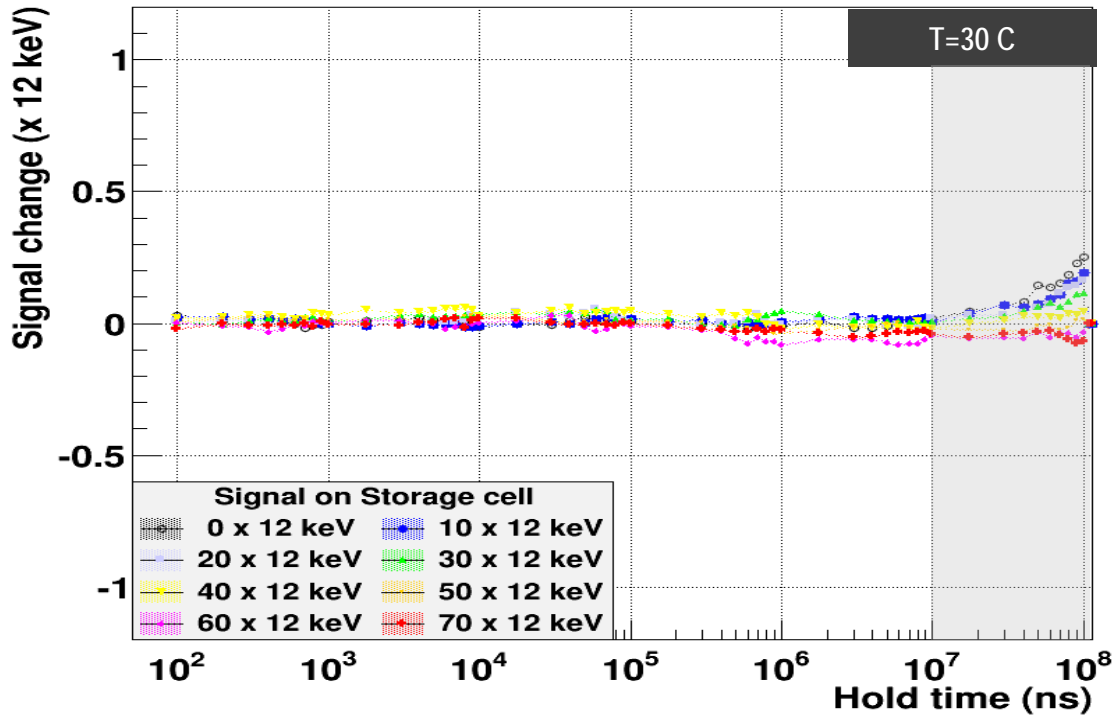


- Typical Hold Time on Storage Cell: 10 – 100 ms (Depending on readout speed)
- Two random pixels
- Temperature: 50 C
- Analog signal droops between (-0.6 .. +0.5) x12 keV photons

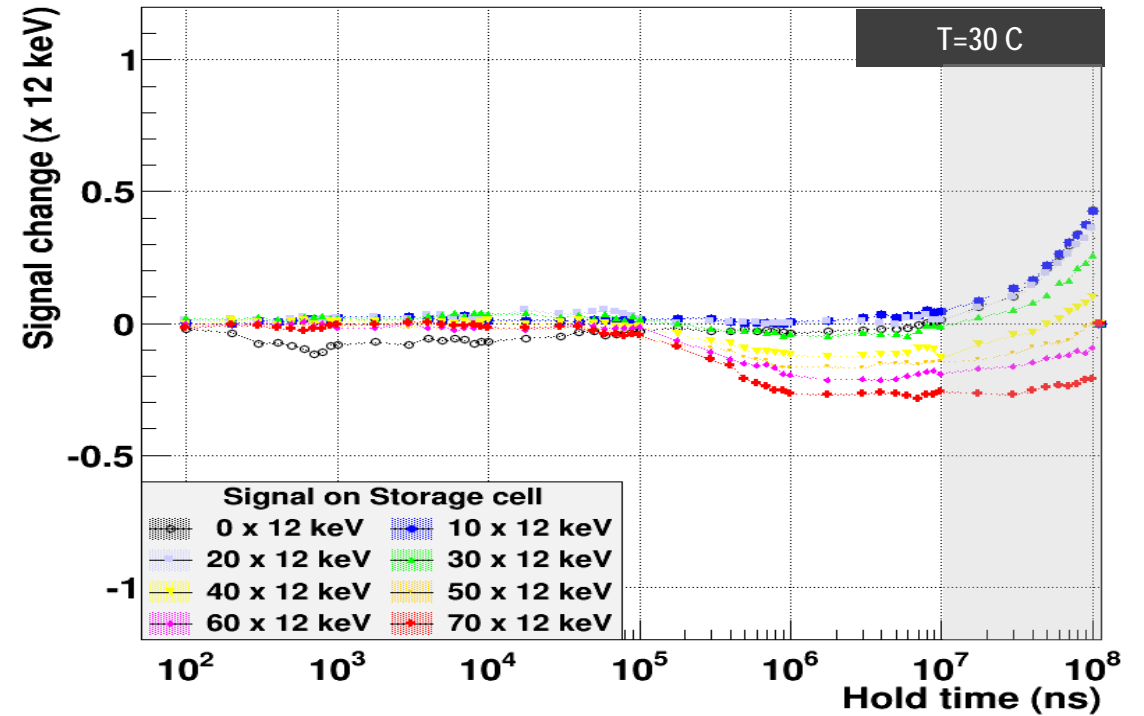
Droop of the analog Storage Cells (T=30 C)



Pixel 325 – Storage Cell 66 - Droop (x12 keV, CDS gain HIGH)



Pixel 1825 – Storage Cell 66 - Droop (x12 keV, CDS gain HIGH)



- Typical Hold Time on Storage Cell: 10 – 100 ms (Depending on readout speed)
- Two random pixels
- Temperature: 30 C
- Analog signal droops between (-0.2 .. +0.4) x12 keV photons
- Cooling helps dramatically

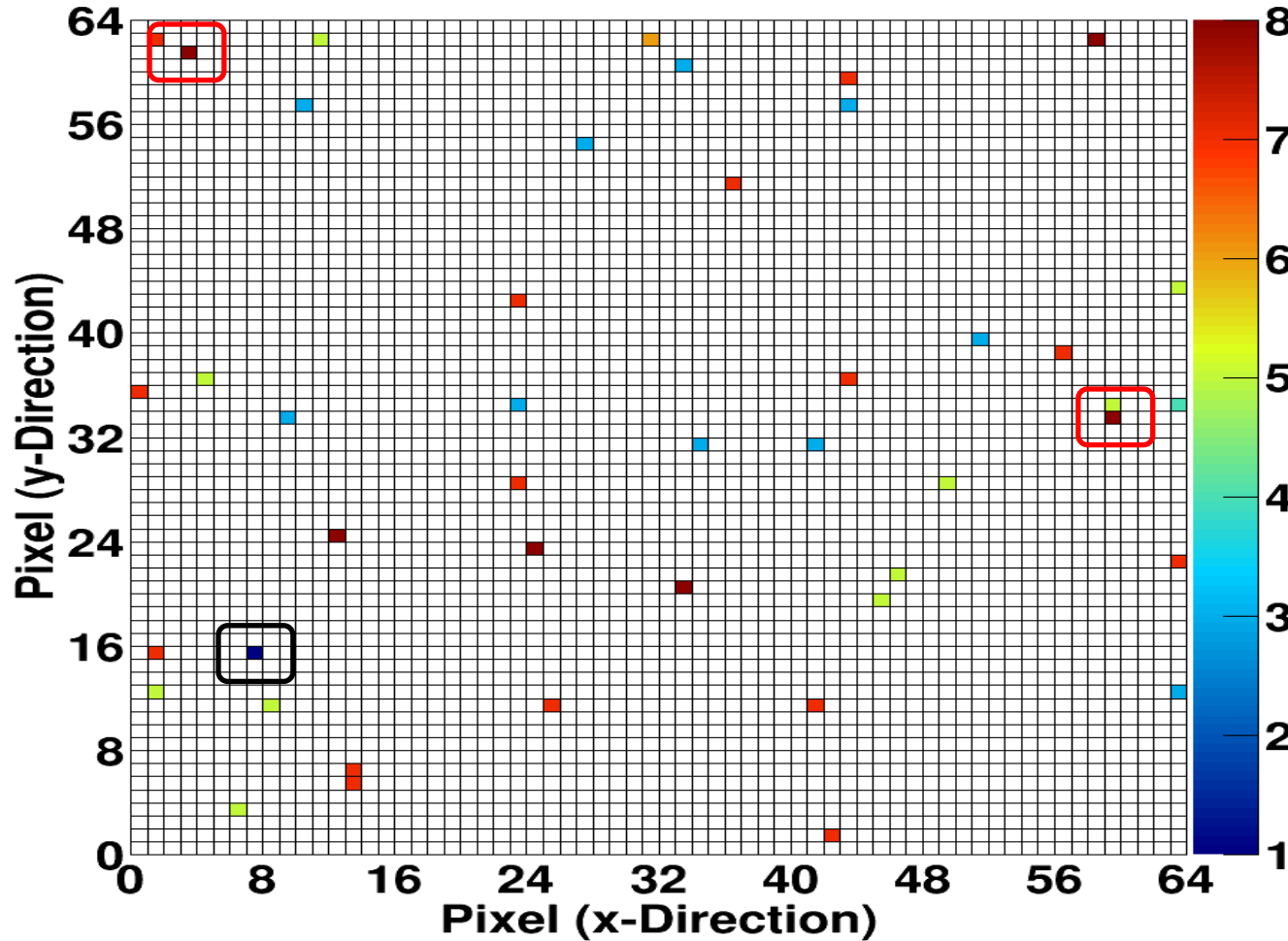


5

Chip Probing / Bumpbond



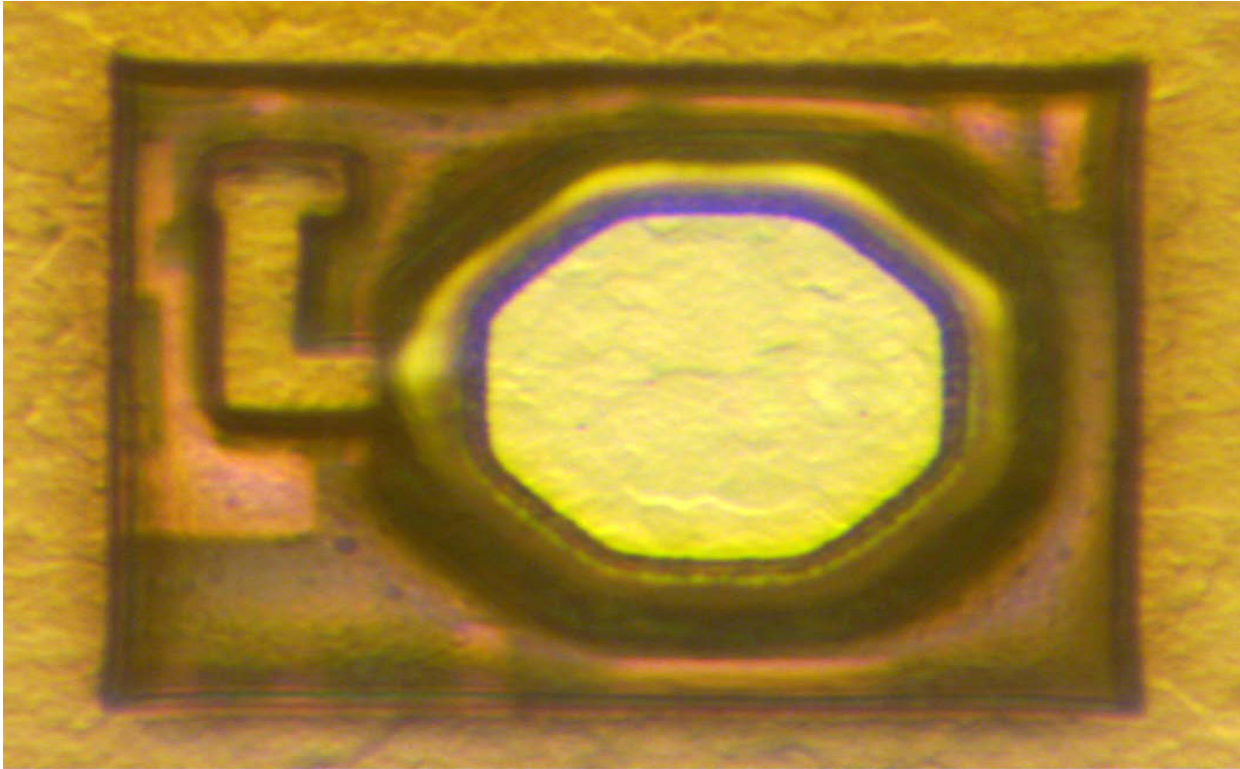
AGIPD1.0 – Chip001 – Pixel Failure Map



Failure codes:

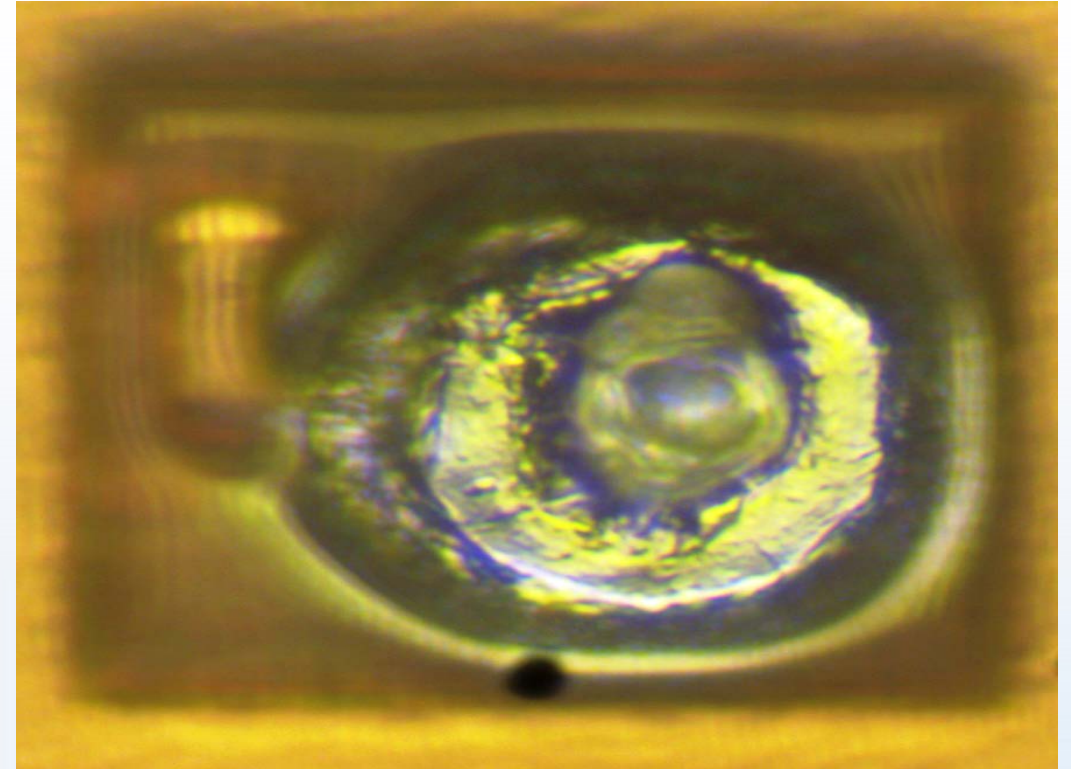
- Electronically dead
- Testpulse capacitors broken
- Current source (mainly whole SC Rows, potentially crosstalk)
- Storage Cell Row: Failed
- Single Storage Cells: Failed
- Low X-Ray Gain, but working
- ,No Photon Peak' (e.g. Sensor processing) but baseline off
- Bumpbonding Issue

-
- 41 Pixels fail due to various reasons
 - 38 Pixel fail the tests with X-Rays, but only 2 of these pixels fail due to bumpbonding
 - Bumpbond Yield: 99.95 %



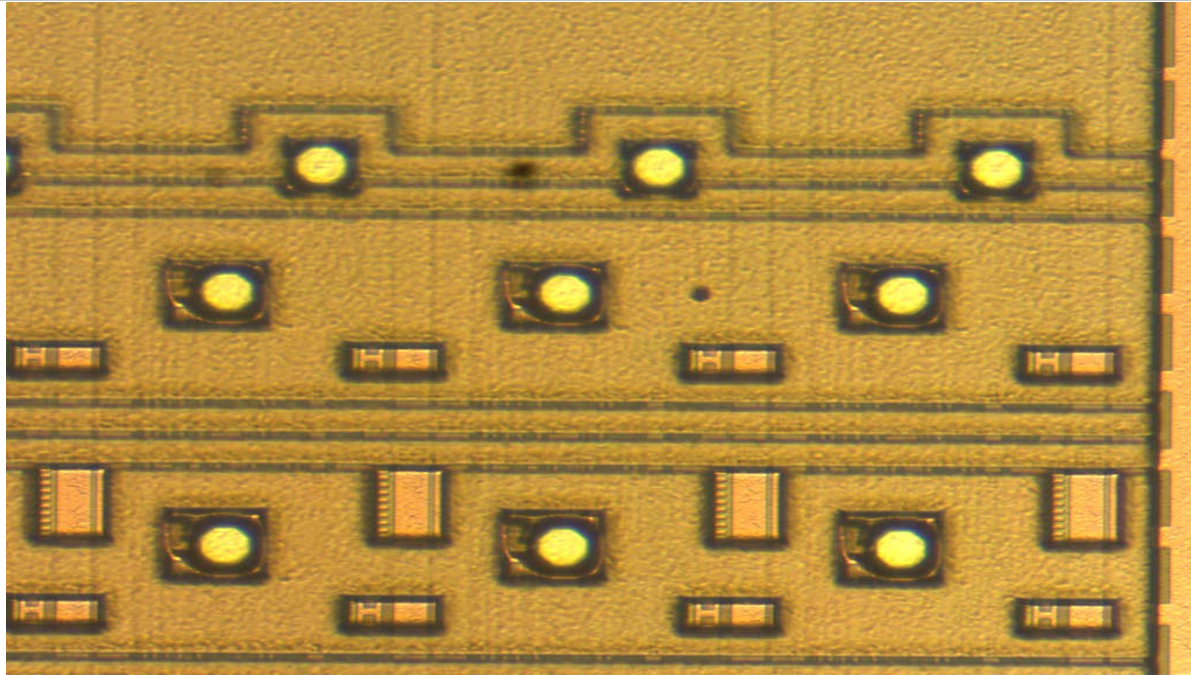
Processed ASIC – UBM visible

→ No indium on the ASIC side



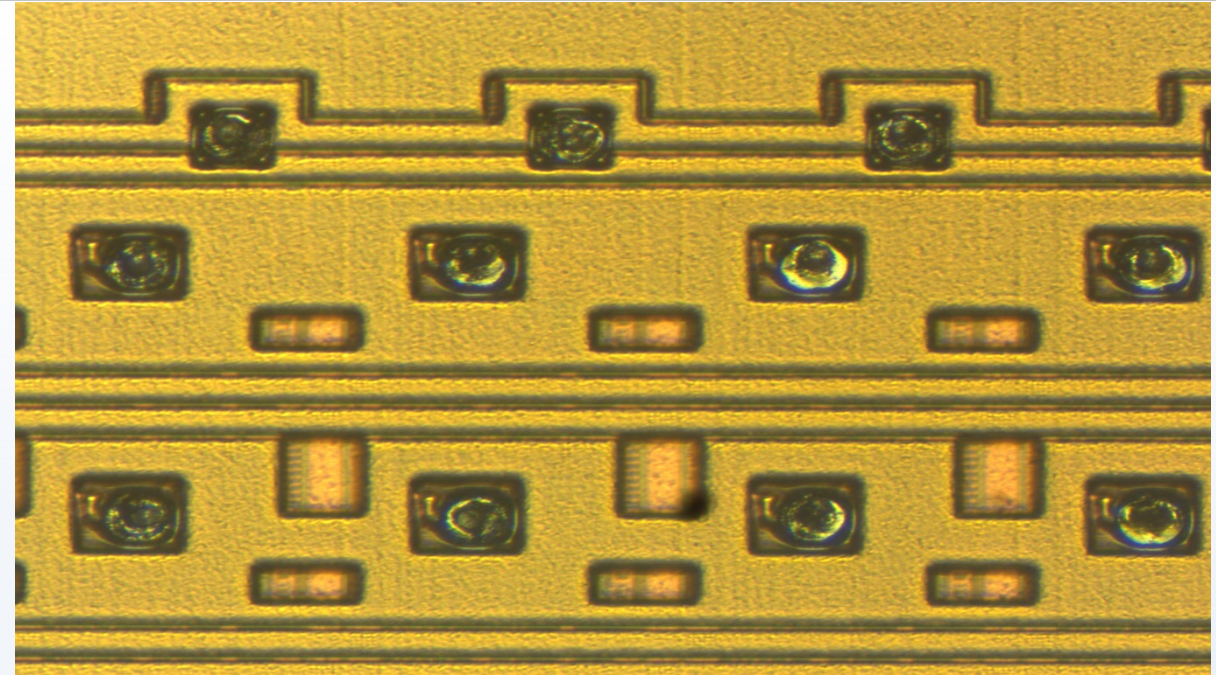
Ripped of ASIC – Indium residuals

→ Indium connection existed
→ 'Random' point of disruption



Processed ASIC – UBM visible

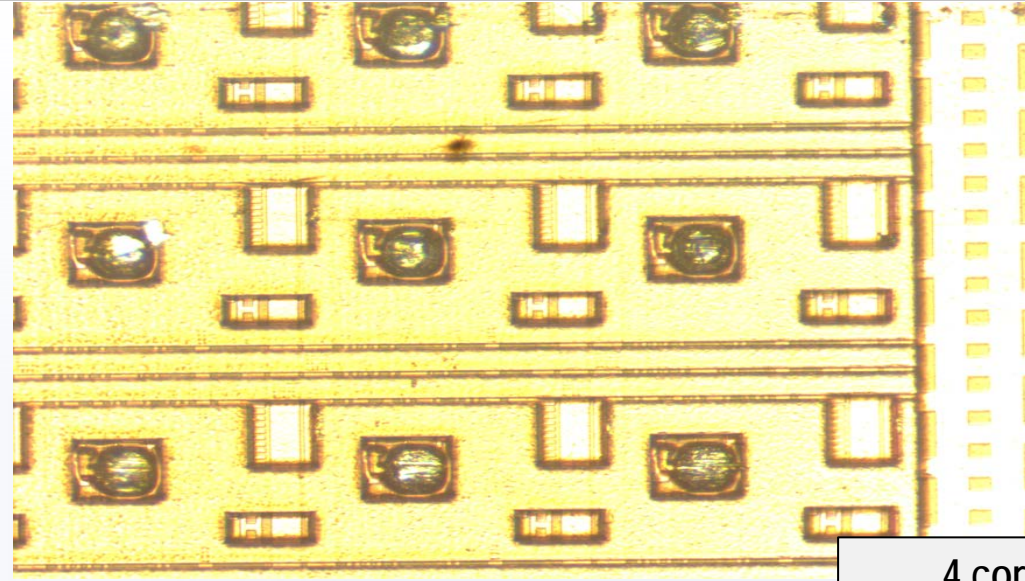
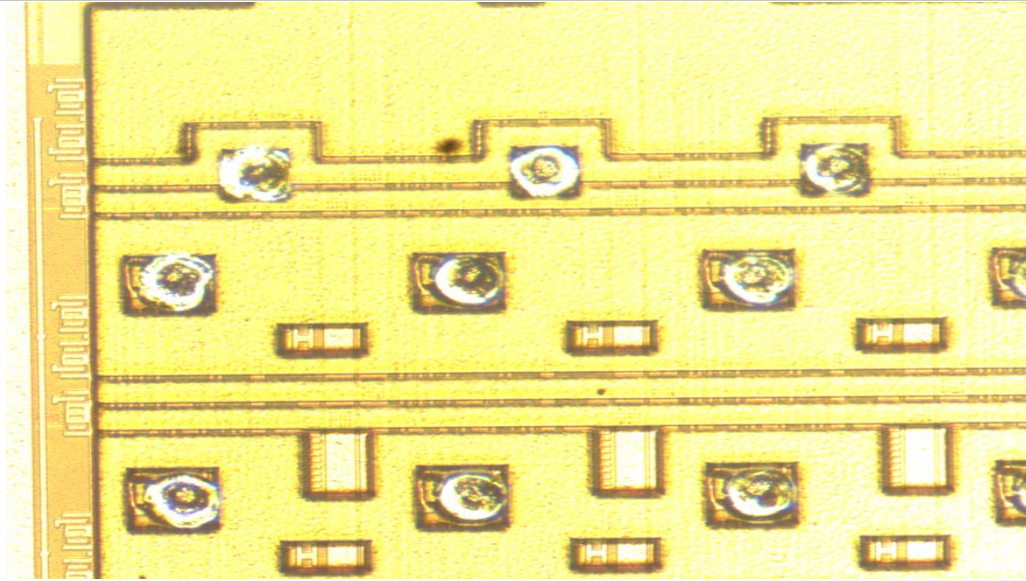
→ No indium on the ASIC side



Ripped of ASIC – Indium residuals

→ Indium connection existed
→ 'Random' point of disruption

Chip- / Module Probing: Ripped off module



4 corners of the module,
all were connected

